

WISMO Quik Q2400 series

Q2406 and Q2426 Product Specification

Reference: **WM_PRJ_Q2400_PTS_002**
Revision: **002**
Date: **24th January 2003**



Document Information

| Revision | Date | History of the evolution | |
|----------|------------|---|--|
| 001 | 24 Oct 02 | Creation (Preliminary version) | |
| 002 | 24 Jan. 03 | Remove "Preliminary" status. Modification in applicable products list: <ul style="list-style-type: none">• Add Q2406D and Q2426D products and Q2406E and Q2426E products• Remove Q2406C and Q2426C products Update sensitivity value for GSM850 and EGSM900 RF bands. Update mechanical drawing. | |

Overview

This document defines and specifies the WISMO QUIK Q24x6 Series, available under two GSM/GPRS CI10 bi band versions:

- **Q2406A:** EGSM/GPRS **900/1800** MHz version with **16** Mb of Flash memory and **2** Mb of SRAM (16/2)
- **Q2406B:** EGSM/GPRS **900/1800** MHz version with **32** Mb of Flash memory and **4** Mb of SRAM (32/4)
- **Q2406D:** EGSM/GPRS **900/1800** MHz version with **64** Mb of Flash memory and **8** Mb of SRAM (64/8). This configuration will be available for handset application and vertical application where UART2 is not used.
- **Q2406E:** EGSM/GPRS **900/1800** MHz version with **64** Mb of Flash memory and **4** Mb of SRAM (64/4). This configuration will be available for handset application and vertical application where UART2 is not used.
- **Q2426A:** EGSM/GPRS **850/1900** MHz version with **16** Mb of Flash memory and **2** Mb of SRAM (16/2)
- **Q2426B:** EGSM/GPRS **850/1900** MHz version with **32** Mb of Flash memory and **4** Mb of SRAM (32/4)
- **Q2426D:** EGSM/GPRS **850/1900** MHz version with **64** Mb of Flash memory and **8** Mb of SRAM (64/8). This configuration will be available for handset application and vertical application where UART2 is not used.
- **Q2426E:** EGSM/GPRS **850/1900** MHz version with **64** Mb of Flash memory and **4** Mb of SRAM (64/4). This configuration will be available for handset application and vertical application where UART2 is not used.

Contents

| | |
|--|-----------|
| Document Information..... | 2 |
| Overview | 3 |
| Contents..... | 4 |
| Caution..... | 8 |
| Trademarks | 8 |
| 1 General description..... | 9 |
| 1.1 General information..... | 9 |
| 1.2 Functional description | 10 |
| 1.2.1 RF functionalities..... | 11 |
| 1.2.2 Baseband functionalities..... | 11 |
| 1.3 Firmware..... | 11 |
| 2 Interfaces | 12 |
| 2.1 General Purpose Connector (GPC) | 12 |
| 2.2 Power supply | 13 |
| 2.2.1 Power supply description | 13 |
| 2.2.2 Power consumption | 14 |
| 2.3 Electrical information for digital I/O..... | 16 |
| 2.4 LCD interface..... | 17 |
| 2.4.1 SPI bus..... | 17 |
| 2.4.2 Two wires interface..... | 17 |
| 2.5 SPI Auxiliary bus | 17 |
| 2.6 Keyboard interface..... | 18 |
| 2.7 Main serial link (UART1)..... | 18 |
| 2.7.1 Typical implementation with a RS232 Terminal..... | 20 |
| 2.7.2 Typical implementation with a microprocessor | 21 |
| 2.8 Auxiliary serial link (Uart2)..... | 21 |
| 2.9 SIM interface..... | 22 |
| 2.9.1 General Description | 22 |
| 2.9.2 SIM socket connection | 24 |
| 2.9.3 SIM 3/5V management..... | 24 |

| | | |
|------------|--|----|
| 2.10 | General Purpose Input/Output | 25 |
| 2.11 | Analog to Digital Converter..... | 27 |
| 2.12 | Audio interface | 27 |
| 2.12.1 | Microphone inputs | 27 |
| 2.12.1.1 | Common microphone inputs characteristics | 28 |
| 2.12.1.2 | Main Microphone Inputs (MIC2)..... | 30 |
| 2.12.1.3 | Auxiliary Microphone Inputs (MIC1) | 31 |
| 2.12.1.3.1 | Differential connection | 31 |
| 2.12.1.3.2 | Single-ended connection..... | 32 |
| 2.12.2 | Common speaker outputs characteristics | 33 |
| 2.12.2.1 | Differential Connection..... | 33 |
| 2.12.2.2 | Single-ended Connection | 33 |
| 2.12.3 | Speaker outputs | 35 |
| 2.12.3.1 | Speaker 2 Outputs..... | 35 |
| 2.12.3.2 | Speaker 1 Outputs..... | 35 |
| 2.12.4 | Buzzer Output | 35 |
| 2.13 | Battery charging interface | 36 |
| 2.13.1 | Li-ion charging procedure | 38 |
| 2.13.2 | How to define R1 and C1 | 38 |
| 2.14 | ON / ~OFF | 39 |
| 2.14.1 | Operating sequences | 40 |
| 2.14.1.1 | Power ON..... | 40 |
| 2.14.1.2 | Power OFF..... | 41 |
| 2.15 | BOOT (optional)..... | 41 |
| 2.16 | Reset signal (~RST)..... | 42 |
| 2.16.1 | Reset sequence | 44 |
| 2.17 | External Interrupt (~INTR) | 44 |
| 2.18 | VCC output | 45 |
| 2.19 | VCC_RTC (Real Time Clock Supply)..... | 45 |
| 2.19.1 | Interface description | 45 |
| 2.19.2 | Typical implementation..... | 46 |
| 2.19.2.1 | Capacitor | 46 |
| 2.19.2.2 | Super Capacitor | 46 |
| 2.19.2.3 | Battery cell with regulator..... | 47 |
| 2.19.2.4 | Non Rechargeable battery..... | 47 |
| 2.20 | RF interface | 48 |
| 2.20.1 | RF connections | 48 |
| 2.20.2 | RF performances | 48 |
| 2.20.3 | Antenna specifications | 49 |

| | | |
|----------|--|-----------|
| 3 | Technical specifications | 50 |
| 3.1 | General Purpose Connector pin out description | 50 |
| 3.2 | Environmental Specifications..... | 54 |
| 3.3 | Mechanical specifications..... | 55 |
| 3.3.1 | Physical characteristics..... | 55 |
| 3.3.2 | Mechanical drawings | 55 |
| 4 | Connectors and peripheral devices references..... | 57 |
| 4.1 | General Purpose Connector | 57 |
| 4.2 | SIM Card Reader | 57 |
| 4.3 | Microphone..... | 57 |
| 4.4 | Speaker | 58 |
| 4.5 | Antenna Cable..... | 58 |
| 4.6 | GSM antenna | 58 |
| 5 | Design Guidelines | 59 |
| 5.1 | HARDWARE and RF | 59 |
| 5.1.1 | EMC recommendations | 59 |
| 5.1.2 | Power Supply | 59 |
| 5.1.3 | Layout requirement | 60 |
| 5.1.4 | Antenna..... | 62 |
| 5.2 | Mechanical integration | 62 |
| 5.3 | Firmware upgrade..... | 62 |
| 5.3.1 | Nominal upgrade procedure | 62 |
| 5.3.2 | Backup procedure..... | 63 |
| 6 | Appendix..... | 64 |
| 6.1 | Wavecom acceptance test..... | 64 |
| 6.2 | Standards and Recommendations..... | 66 |
| 6.3 | Safety recommendations (for information only) | 69 |
| 6.3.1 | RF safety | 69 |
| 6.3.1.1 | General | 69 |
| 6.3.1.2 | Exposure to RF energy..... | 69 |
| 6.3.1.3 | Efficient terminal operation | 69 |
| 6.3.1.4 | Antenna care and replacement | 70 |
| 6.3.2 | General safety..... | 70 |
| 6.3.2.1 | Driving..... | 70 |
| 6.3.2.2 | Electronic devices | 70 |
| 6.3.2.3 | Vehicle electronic equipment | 70 |
| 6.3.2.4 | Medical electronic equipment | 70 |
| 6.3.2.5 | Aircraft | 71 |
| 6.3.2.6 | Children | 71 |
| 6.3.2.7 | Blasting areas..... | 71 |
| 6.3.2.8 | Potentially explosive atmospheres | 71 |

| | | |
|-------|---|----|
| 6.4 | Application notes for the SIM interface..... | 72 |
| 6.4.1 | Application note #1 : interfacing 3V SIMs..... | 73 |
| 6.4.2 | Application note #2 : interfacing 3V/5V SIMs..... | 74 |
| 6.5 | General Purpose Connector data sheet..... | 75 |

Caution

Information furnished herein by Wavecom are accurate and reliable. However no responsibility is assumed for its use. Please read carefully the safety precautions for a terminal based on WISMO Quik Q24x6 Series.

General information about Wavecom and its range of products is available at the following internet address: <http://www.wavecom.com>

Trademarks

Some mentioned products are registered trademarks of their respective companies.

1 General description

1.1 General information

WISMO Quik Q24x6 is a self-contained E-GSM/GPRS 900/1800 or 850/1900 bi-band module including the following features :

- 58.4 x 32.2 x 3.9 mm
- 2 Watts EGSM 900/GSM 850 radio section running under 3.6 Volts
- 1 Watt GSM1800/1900 radio section running under 3.6 Volts
- Digital section running under 2.8 Volts
- 3V SIM interface
- Real Time Clock with calendar
- Battery charger
- Echo Cancellation + noise reduction
- Full GSM or GSM/GPRS software stack
- Hardware GPRS class 10 capable
- Complete shielding
- Complete interfacing :
 - Power supply
 - Serial link
 - Audio
 - SIM card
 - Keyboard
 - LCD (not available with AT commands)

WISMO Quik Q24x6 Series has two external connections :

- RF connection pads (to the antenna)
- General Purpose Connector (GPC) to Digital, Keyboard, Audio and Supply

WISMO Quik Q24x6 Series is designed to fit in very small terminals and only some custom functions have to be added to make a complete bi-band solution:

- Keypad and LCD module
- Earpiece and Microphone
- Base connector
- Battery
- Antenna switch
- SIM connector

1.2 Functional description

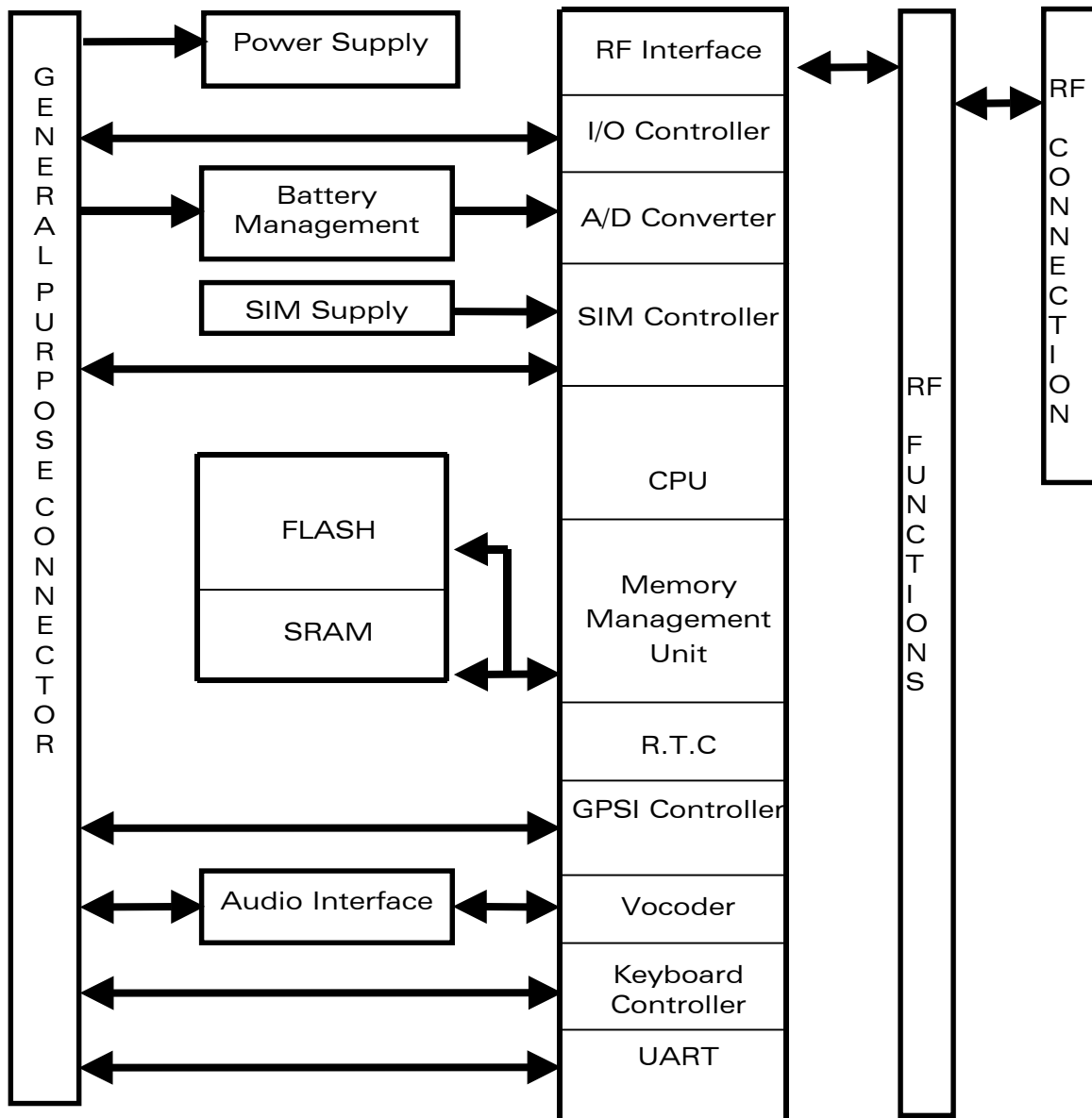


Figure 1 : Functional architecture

1.2.1 RF functionalities

The Radio Frequency (RF) functionalities comply with the Phase II EGSM 900/GSM 1800 and GSM 850/GSM 1900 recommendation. The frequencies are :

Q2406

- Rx (EGSM 900): 925 to 960 MHz Rx (GSM 1800): 1805 to 1880 MHz
- Tx (EGSM 900): 880 to 915 MHz Tx (GSM 1800): 1710 to 1785 MHz

Q2426

- Rx (EGSM 850) : 869 to 894 MHz Rx (GSM 1900) : 1930 to 1990 MHz
- Tx (EGSM 850) : 824 to 849 MHz Tx (GSM 1900) : 1850 to 1910 MHz

The Radio Frequency (RF) part is based on a specific dual band chip including :

- Low-if Receiver
- Dual RF (Radio Frequency) synthesizer
- Digital if to Baseband Converter
- Offset PLL (Phase Lock Loop) transmitter
- 1 (logarithmic) Power Amplifier (PA) controller
- Dual band (Power Amplifier (PA) module

1.2.2 Baseband functionalities

The digital part of the WISMO Quik Q24x6 Series is composed of a PHILIPS-VLSI chip (ONE C GSM/GPRS Kernel). This chipset is using a 0,25 μ m mixed technology CMOS, which allows massive integration as well as low current consumption.

1.3 Firmware

WISMO Quik Q24x6 Series is designed to be integrated into various types of applications such as handsets or vertical applications (telemetry, multimedia,...).


For vertical applications, the firmware offers a set of AT commands to control the module. With this standard software, some interfaces of the module are not available since they are dependent on the peripheral devices connected to the module. They are the LCD interface and the SPI bus.

2 Interfaces

2.1 General Purpose Connector (GPC)

A 60 pins connector¹ is provided to interface the WISMO Quik Q24x6 Series with a board containing either a LCD module, or a keyboard, or a SIM connector, or a battery connection...

The interfaces available on the GPC are described in the next paragraphs.

 Please be aware that some of these interfaces can not be handled when using the WISMO Quik Q24x6 Series driven by AT commands : LCD interface, SPI bus.



This symbol is used to indicate the interfaces not available with AT commands.

These functions have then to be managed externally i.e using the main processor of the application.

¹ The communication interface connector is a 60 pins connector with 0.5mm pitch from KYOCERA / AVX group with the following reference (see chapter connectors reference for further details):

14 5087 060 930 861.

The matting connector has the following reference :

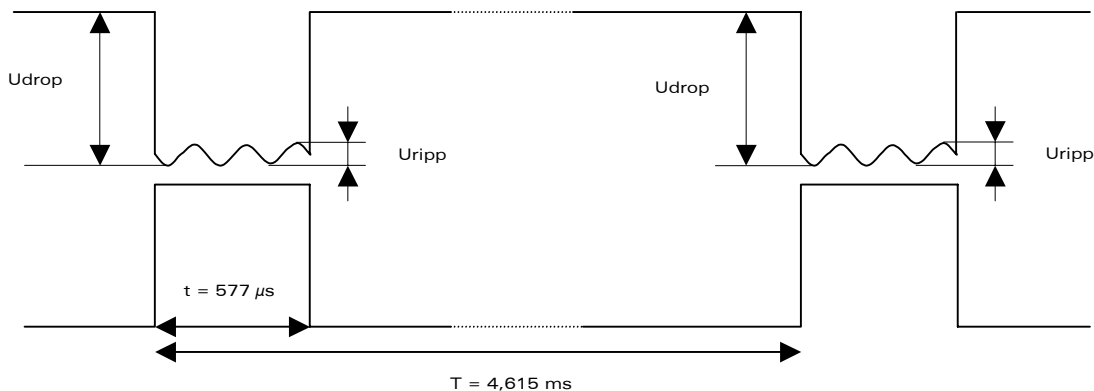
24 5087 060 X00 861.

2.2 Power supply

2.2.1 Power supply description

The power supply is one of the key issue in the design of a GSM terminal. Due to the bursted emission in GSM / GPRS, the power supply must be able to deliver high current peaks in a short time. During these peaks the ripple (U_{ripp}) and the drop (U_{drop}) on the supply voltage must not exceed a certain limit (see table "Power Supply Voltage" bellow).

- In communication mode, a GSM/GPRS classe 2 terminal emits $577\mu s$ radio bursts every 4.615ms.



In communication mode, a GPRS class 10 terminal emits $1154\mu s$ radio bursts every 4.615ms.

Two different inputs are provided for the power supply. The first one, VBATT is used to supply the RF part and VDD, the second one is used to supply the baseband part.

Notes :

- It is possible to connect VBATT to VDD.
- In case of separate power supplies, they have to be in the same state i.e both active or inactive at the same time.

VBATT : supplies directly the RF components with 3,6 V. It is essential to keep a minimum voltage ripple at this connection in order to avoid any phase error. The RF Power Amplifier current (2.0 A peak in GSM /GPRS mode) flows with a ratio of 1/8 of the time (around $577\mu s$ every 4.615ms for GSM /GPRS cl 2) and 2/8 of the time (around $1154\mu s$ every 4.615ms for GSM /GPRS cl 10). The rising time is around $10\mu s$.

VDD : supplies the +2.8V ballast regulators of the WISMO QUIK Q24x6. It is essential to keep the voltage over 3.1 volts.

The WISMO QUIK Q24x6 Series shielding case is the grounding. The ground has to be connected on the mother board through a complete layer on the PCB.

Power Supply Voltage

| | V _{MIN} | V _{NOM} | V _{MAX} | Ripple max (U _{ripp}) |
|-------|------------------|------------------|------------------|---|
| VBATT | 3.3 V (*) | 3.6 V | 4.5 V (**) | 50 mVpp for freq<200kHz 500 µVpp for freq>200kHz |
| VDD | 3.1 V | | 4.5 V | 100 mVpp |

(*) : This value has to be guaranteed during the burst (with 2.0A Peak in GSM or GPRS mode)

(**) : max operating Voltage Stationary Wave Ratio (VSWR) 2:1

When supplying the module with a battery, the total impedance (battery+protections+PCB) should be <150 mOhms

2.2.2 Power consumption

Following information are given assuming a 50 Ω RF output.

Power consumption in OFF mode (module supplied, OFF state, no software running)

| | Conditions | I _{NOM} | I _{MAX} |
|---------------------|------------|------------------|------------------|
| Overall consumption | Off | 5 µA | 10 µA |

**Power consumption in EGSM/GPRS 900 MHz and GSM/GPRS 850 MHz mode
classe 10**

| | Conditions | I _{NOM} | I _{MAX} |
|-------|---------------------------------------|------------------|------------------|
| VBATT | During TX bursts @Pcl5 | 1.7 A peak | 2.0 A peak |
| VBATT | During RX bursts | 75 mA peak | 80 mA peak |
| VBATT | Average 1Rx/1Tx @Pcl5 | 270 mA | 320 mA |
| VBATT | Average 1Rx/1Tx @Pcl8 | 180 mA | 200 mA |
| VBATT | Average Idle mode | 100 μ A | 300 μ A |
| VBATT | Average GPRS Cl 10 (3Rx/2Tx) @Pcl5 | 540 mA | 640 mA |
| VBATT | Average GPRS Cl 10 (3Rx/2Tx) @Pcl8 | 360 mA | 400 mA |
| VDD | Average Idle mode | 2,2 mA | 3 mA |

Power Control Level : Pcl5=2W typ. ; Pcl8=0,5W typ.

**Power consumption in GSM/GPRS 1800 MHz and
GSM/GPRS 1900 MHz mode classe 10**

| | Conditions | I _{NOM} | I _{MAX} |
|-------|---------------------------------------|------------------|------------------|
| VBATT | During TX bursts @Pcl0 | 1.3 A peak | 1.7 A peak |
| VBATT | During RX bursts | 75 mA peak | 80 mA peak |
| VBATT | Average 1Rx/1Tx @Pcl0 | 240 mA | 270 mA |
| VBATT | Average 1Rx/1Tx @Pcl3 | 150 mA | 180 mA |
| VBATT | Average Idle mode | 100 μ A | 300 μ A |
| VBATT | Average GPRS Cl 10 (3Rx/2Tx) @Pcl0 | 480 mA | 540 mA |
| VBATT | Average GPRS Cl 10 (3Rx/2Tx) @Pcl3 | 300 mA | 360 mA |
| VDD | Average Idle mode | 2,2 mA | 3 mA |

Power Control Level : Pcl0=1W typ. ; Pcl3=0,25W typ.

Power Supply Pinout

| Signal | Pin number |
|--------|-------------------|
| VBATT | 55, 57, 58, 59 60 |
| VDD | 11 |
| GND | Shielding |

The grounding connection is done through the shielding ⇒ the four legs have to be soldered to the ground plane.

2.3 Electrical information for digital I/O

All digital I/O comply with 3Volts CMOS.

Operating conditions

| Parameter | I/O type | Min | Max | Condition |
|-----------|----------|--------|-------|--------------------------|
| V_{IL} | CMOS | -0.5 V | 0.8 V | |
| V_{IH} | CMOS | 2.1 V | 3.0 V | |
| V_{OL} | 1X | | 0.2 V | $I_{OL} = -1 \text{ mA}$ |
| | 2X | | 0.2 V | $I_{OL} = -2 \text{ mA}$ |
| | 3X | | 0.2 V | $I_{OL} = -3 \text{ mA}$ |
| V_{OH} | 1X | 2.6 V | | $I_{OH} = 1 \text{ mA}$ |
| | 2X | 2.6 V | | $I_{OH} = 2 \text{ mA}$ |
| | 3X | 2.6 V | | $I_{OH} = 3 \text{ mA}$ |

To interface the WISMO Quik Q24x6 Series digital signals with other logics :

- 3V logic : some serial resistors (between 2.2K and 4.7Kohms) can be added on the lines
- 3.3V logic : some serial resistors (between 4.7K and 10Kohms) can be added on the lines.
- For higher voltage logics, a resistor bridge or a level shifter IC can be added.



2.4 LCD interface

The WISMO Quik Q24x6 Series can be connected to a LCD module driver through either a SPI bus or a two wires interface.

2.4.1 SPI bus

The SPI bus includes a CLK signal, an IO signal and an EN signal complying with SPI bus standard.

Pin description

| Signal | Pin number | I/O | I/O type | Description |
|----------|------------|-----|-----------|------------------|
| SPI_CLK | 10 | O | 1X | SPI Serial Clock |
| SPI_IO | 8 | I/O | CMOS / 1X | SPI Data |
| SPI_EN * | 28 | O | 1X | SPI Enable |

* Multiplexed with GPO3.

2.4.2 Two wires interface

The two wires interface includes a CLK signal and a DATA signal complying with a standard 96KHz interface. The maximum speed transfer is 400Kb/s.

Pin description

| Signal | Pin number | I/O | I/O type | Description |
|--------|------------|-----|-----------|--------------|
| SCL | 10 | O | 1X | Serial Clock |
| SDA | 8 | I/O | CMOS / 1X | Data |



2.5 SPI Auxiliary bus

A second SPI Chip Enable (called SPI_AUX) has to be used to add a SPI peripheral to the WISMO Quik Q24x6 Series.

Pin description

| Signal | Pin number | I/O | I/O type | Description |
|-----------|------------|-----|-----------|------------------|
| SPI_CLK | 10 | O | 1X | SPI Serial Clock |
| SPI_IO | 8 | I/O | CMOS / 1X | SPI Data |
| SPI_AUX * | 26 | O | 1X | SPI Aux. Enable |

* Multiplexed with GPO0.

2.6 Keyboard interface

Warning :

This interface is not FULLY available with AT commands :

An AT command allows to get the input key code (see +CMER command description). This code has then to be processed by the application.

This interface provides 10 connections : 5 rows (R0 to R4) and 5 columns (C0 to C4).

The scanning is a digital one , and the debouncing is done in the WISMO Quik Q24x6 Series. No discrete components like R,C (Resistor, Capacitor) are needed.

Pin description

| Signal | Pin number | I/O | I/O type | Description |
|--------|------------|-----|-----------|-------------|
| ROW0 | 13 | I/O | CMOS / 1X | Row scan |
| ROW1 | 15 | I/O | CMOS / 1X | Row scan |
| ROW2 | 17 | I/O | CMOS / 1X | Row scan |
| ROW3 | 19 | I/O | CMOS / 1X | Row scan |
| ROW4 | 21 | I/O | CMOS / 1X | Row scan |
| COL0 | 23 | I/O | CMOS / 1X | Column scan |
| COL1 | 25 | I/O | CMOS / 1X | Column scan |
| COL2 | 27 | I/O | CMOS / 1X | Column scan |
| COL3 | 29 | I/O | CMOS / 1X | Column scan |
| COL4 | 31 | I/O | CMOS / 1X | Column scan |

2.7 Main serial link (UART1)

A flexible 6 wires serial interface is available complying with V24 protocol signalling but not with V28 (electrical interface) due to a 2.8 Volts interface.

The signals are TX data (CT103/TX), RX data (CT104/RX), Request To Send (CT105/RTS), Clear To Send (CT106/CTS), Data Terminal Ready (CT108-2/DTR) and Data Set Ready (CT107/DSR).

The set of RS232 signals can be required for GSM DATA services application and is generated by the general purpose I/O provided by the Q24x6 series. The 2 additional signals are Data Carrier Detect (CT109/DCD) and Ring Indicator (CT125/RI).

Pin description

| Signal | Pin number | I/O | I/O type | Description |
|--------------|----------------|-----|-----------|----------------------|
| CT103/TXD1 | 39 | I | CMOS | Transmit serial data |
| CT104/RXD1 | 32 | O | 1X | Receive serial data |
| CT105/RTS1 | 30 | I | CMOS | Ready To Send |
| CT106/CTS1 | 37 | O | 1X | Clear To Send |
| CT107/DSR1 | 36 | O | 1X | Data Set Ready |
| CT108-2/DTR1 | 34 | I | CMOS | Data Terminal Ready |
| CT109/DCD1 * | 51 | O | CMOS / 2X | Data Carrier Detect |
| CT125/RI1 ** | 54 | O | CMOS / 2X | Ring Indicator |
| CT102/GND | Shielding legs | | | Ground |

* Multiplexed with GPIO3

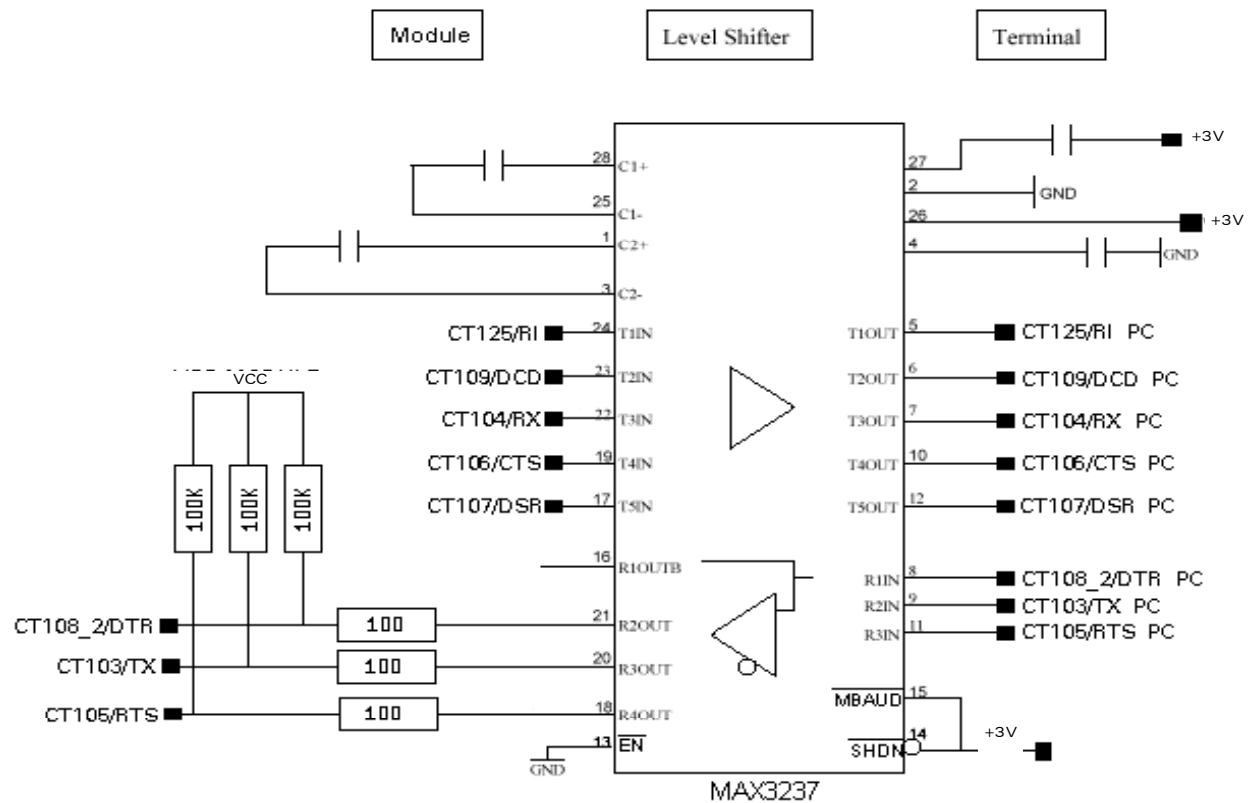
** Multiplexed with GPIO2.

The rising time and falling time of the reception signals (mainly CT103) have to be less than 200 ns.

The Q24x6 Series have been designed to be operated using all the serial interface signals. In particular, it is necessary to use RTS and CTS for hardware flow control in order to avoid data corruption during transmission.

2.7.1 Typical implementation with a RS232 Terminal

The figure above shows a typical implementation when the Q24x6 Module is connected to a RS232 Terminal.

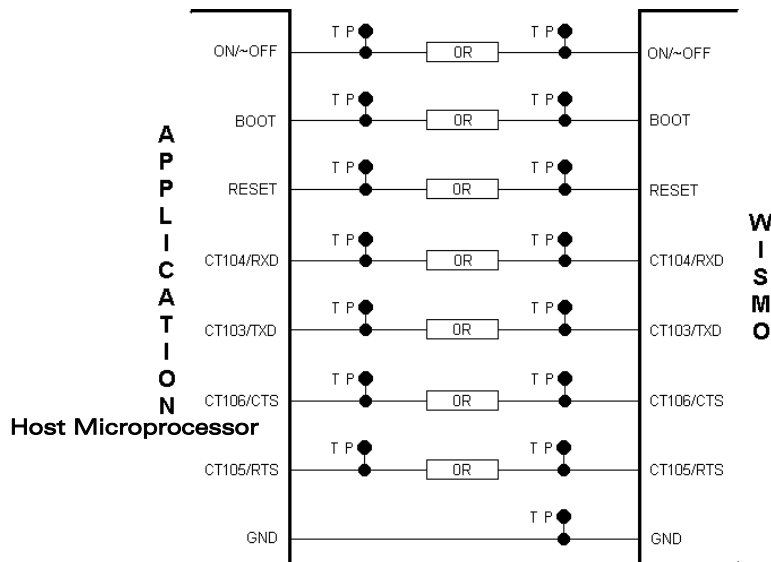


WARNING:

The application must allow the WISMO serial link signals + the BOOT, the RESET and the ON/OFF module signals to be easily accessed thus allowing the module firmware to be upgraded.

2.7.2 Typical implementation with a microprocessor

The figure above shows a typical implementation when the Q24x6 Module is connected to a host microprocessor which is 2,8 V tolerant on the serial port signals.



2.8 Auxiliary serial link (Uart2)

For future applications (e.g. Bluetooth connectivity) an auxiliary serial interface (UART2) will be available on Q24x6A and Q24x6B products.

Warning :

The auxiliary serial link (UART2) is not available on Q24x6D and Q24x6E products (version with 64 Mb of Flash memory and 8 Mb of SRAM).

Pin description

| Signal | Pin number | I/O | I/O type | Description | Multiplexed with |
|--------------|------------|-----|----------|----------------------|------------------|
| CT104 / TXD2 | 18 | I | 3X | Receive serial data | GPI |
| CT103 / RXD2 | 20 | O | CMOS | Transmit serial data | GPO2 |
| CT106 / CTS2 | 24 | I | CMOS | Clear To Send | GPI00 |
| CT105 / RTS2 | 35 | O | 2X | Ready To Send | GPI05 |

2.9 SIM interface

2.9.1 General Description

5 signals exist :

- SIMVCC : SIM power supply.
- SIMRST : reset.
- SIMCLK : clock.
- SIMDATA : I/O port.
- SIMPRES : SIM card detect.

The SIM interface controls a 3V SIM (and a 5V SIM through an external SIM driver). This interface is fully compliant with GSM 11.11 recommendations concerning SIM functions.

It is recommended to add Transient Voltage Suppressor diodes on the signal connected to the SIM socket in order to prevent any ElectroStatic Discharge. TVS diodes with low capacitance (less than 10pF) have to be connected on SIMCLK and SIMDATA to avoid any disturbance of the rising and falling edge. These types of diodes are mandatory for the Full Type Approval. They shall be placed as close as possible to the SIM socket.

The following references can be used : DALC208SC6 from ST Microelectronics.

Pin description

| Signal | Pin number | I/O | I/O type | Description |
|---------|------------|-----|-----------|------------------|
| SIMCLK | 3 | O | 2X | SIM Clock |
| SIMRST | 5 | O | 2X | SIM Reset |
| SIMDATA | 7 | I/O | CMOS / 3X | SIM Data |
| SIMVCC | 9 | O | | SIM Power Supply |
| SIMPRES | 50 | I | CMOS | SIM Card Detect |

Electrical Characteristics

| Parameter | Conditions | Min | Typ | Max | Unit |
|---------------------------------------|----------------------------|---------------------|------|---------------------|---------|
| SIMDATA V_{IH} | $I_{IH} = \pm 20\mu A$ | $0.7 \times SIMVCC$ | | | V |
| SIMDATA V_{IL} | $I_{IL} = 1mA$ | | | $0.3 \times SIMVCC$ | V |
| SIMRST, SIMDATA SIMCLK V_{OH} | Source current = $20\mu A$ | $SIMVCC - 0.1V$ | | | V |
| SIMRST, SIMDATA SIMCLK V_{OL} | Sink current = $-200\mu A$ | | | 0.1 | V |
| SIMVCC* Output Voltage | $I_{SIMVCC} \leq 6mA$ | 2.70 | 2.80 | 2.85 | V |
| SIMCLK Rise/Fall Time | Loaded with 30pF | | | 50 | ns |
| SIMRST, SIMDATA Rise/Fall Time | Loaded with 30pF | | | 1 | μs |
| SIMCLK Frequency | Loaded with 30pF | | | 3.25 | MHz |

(*) : given for the 3V interface. An external SIM driver is needed to handle 5V SIMs.

Note :

When not used **SIMPRES** has to be tied to VCC.

When used, a low to high transition means that the SIM card is inserted and a high to low transition means that the SIM card is removed.

2.9.2 SIM socket connection

SIM socket pin description

| Signal | Pin number | Description |
|--------|------------|---------------------------------------|
| VCC | 1 | SIMVCC |
| RST | 2 | SIMRST |
| CLK | 3 | SIMCLK |
| CC4 | 4 | VCC module |
| GND | 5 | GROUND |
| VPP | 6 | Not connected |
| I/O | 7 | SIMDATA |
| CC8 | 8 | SIMPRES with 100kΩ pull down resistor |

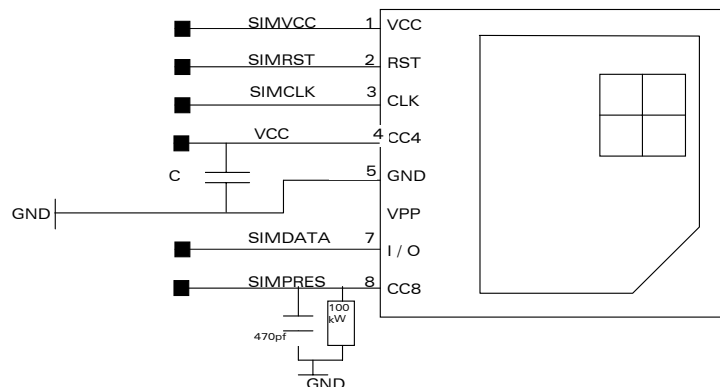


Figure 2 : SIM socket

The capacitor placed on the Sim Vcc must not exceed 470nF.

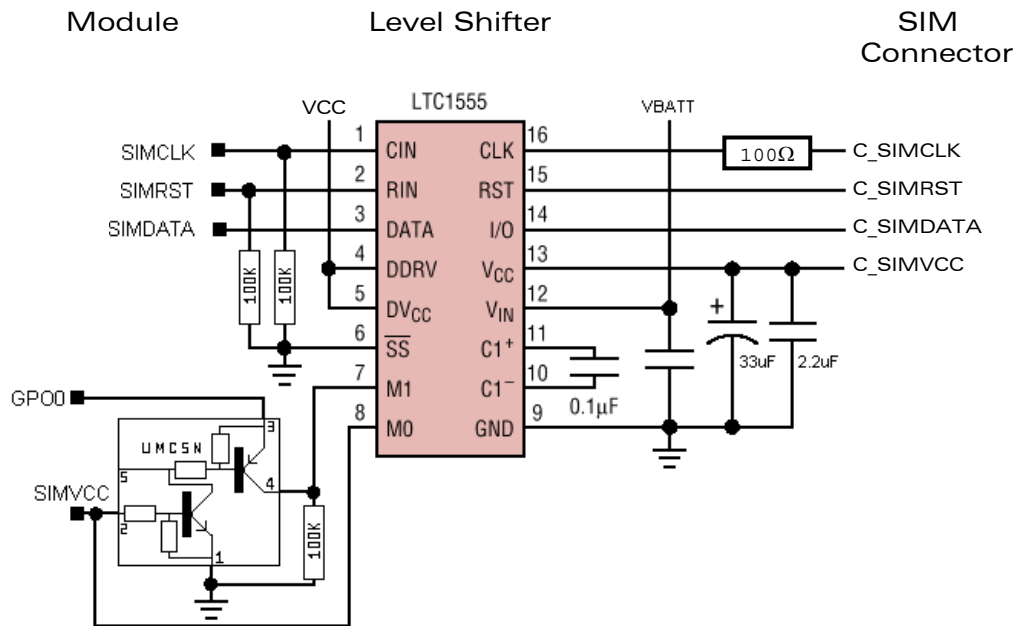
2.9.3 SIM 3/5V management

The WISMO Quik Q24x6 Series module is designed to interface with 3V SIMs only².

Nevertheless, it is possible to manage 3V and 5V SIMs using an external level shifter (see application notes in appendix). In this case, depending on the type of SIM detected, the module firmware triggers the GPO0 output signal (pin #26) in order to properly set the external SIM driver level (3V or 5V).

² Most of the GSM operators have been providing 3V SIMs since 1998.

Typical implementation :



2.10 General Purpose Input/Output

The WISMO Quik Q24x6 Series provides 6 General Purpose I/O, 4 General Purpose Outputs and 1 General Purpose Input. They are used to control any external device such as a LCD or a Keyboard backlight.

Pin description

| Signal | Pin number | I/O | I/O type | Description | Multiplexed with |
|--------|------------|-----|-----------|---------------------|------------------|
| GPI00 | 24 | I/O | CMOS / 2X | General Purpose I/O | RTS2 |
| GPI04 | 53 | I/O | CMOS / 2X | General Purpose I/O | |
| GPI05 | 35 | I/O | CMOS / 2X | General Purpose I/O | CTS2 |
| GPO1 | 22 | O | 3X | General Purpose O | |
| GPO2 | 20 | O | 1X | General Purpose O | TXD2 |
| GPI | 18 | I | CMOS | General Purpose I | RXD2 |
| GPO3 | 28 | O | CMOS | General Purpose O | SPI_EN |



The following GPIOs are not available (reserved) in case of module running with the AT commands firmware :

| Signal | Pin number | I/O | I/O type | Description | Multiplexed with |
|--------|------------|-----|-----------|---------------------|------------------|
| GPIO1 | 52 | I/O | CMOS / 2X | General Purpose I/O | FLASH LED(*) |
| GPIO2 | 54 | I/O | CMOS / 2X | General Purpose I/O | CT125/RI1 |
| GPIO3 | 51 | I/O | CMOS / 2X | General Purpose I/O | CT109/DCD1 |
| GPO0 | 26 | O | 3X | General Purpose O | SPI_AUX |

(*) The FLASH LED signal can be used to drive a LED through an open-collector transistor according to the module activity status.

| LED status | WISMO Quik Q24x6 Series status | |
|------------|---|--|
| OFF | Module in download mode or module OFF | |
| ON | Permanent | Module switched ON, not registered on the network |
| | Slow flash LED ON for 200ms, OFF for 2s | Module switched ON, registered on the network |
| | Quick flash LED ON for 200ms, OFF for 600ms | Module switched ON, registered on the network, communication in progress |

2.11 Analog to Digital Converter

Analog to Digital converter input is provided by the WISMO Quik Q24x6 Series. This converter is a 10 bits one, ranging from 0 to 2.8V .

Pin description

| Signal | Pin number | I/O | I/O type | Description |
|--------|------------|-----|----------|---------------|
| AUXV0 | 33 | I | Analog | A/D converter |

Electrical Characteristics

| Parameter | Min | Max | Unit |
|------------------------|-------|------|------|
| Resolution | 10 | | bits |
| Sampling rate | 90.3 | | Ksps |
| Input signal range | 0 | 2.8V | V |
| ADC Reference Accuracy | 0.75 | 2 | % |
| Integral Accuracy | +/- 1 | | LSB |
| Differential Accuracy | +/- 1 | | LSB |
| Input Impedance (R) | 10 | | MΩ |
| Input Impedance (C) | | 100 | nF |

2.12 Audio interface

Two different microphone inputs and two different speaker outputs are supported.

The WISMO Quik Q24x6 Series also includes an echo cancellation feature which allows handsfree function.

2.12.1 Microphone inputs

The MIC2 inputs already include the biasing for an electret microphone allowing an easy connection to a handset.

The MIC1 inputs do not include an internal bias. MIC1/SPK1 is then appropriate for a hands free system or a handset with biasing external to the module.

2.12.1.1 Common microphone inputs characteristics

The connection can be either differential or single-ended but using a differential connection in order to reject common mode noise and TDMA noise is strongly recommended. When using a single-ended connection, be sure to have a very good ground plane, a very good filtering as well as shielding in order to avoid any disturbance on the audio path.

Internal audio filter characteristics

| Frequency | Gain |
|-------------|---------|
| 0-150 Hz | < -22dB |
| 150-180 Hz | < -11dB |
| 180-200 Hz | < -3dB |
| 200-3700 Hz | 0dB |
| >4000 Hz | < -60dB |

The gain of MIC inputs is internally adjusted and can be tuned from 30dB to 51dB using an AT command.

Microphone gain vs Max input voltage (using controller 1)

| Transmit Gain (dB) | Max Vin (mVrms) | AT+VGT(*) |
|--------------------|-----------------|------------|
| 30 | 43.80 | 0 to 31 |
| 33 | 31.01 | 32 to 63 |
| 36 | 21.95 | 64 to 95 |
| 39 | 15.54 | 96 to 127 |
| 42 | 11 | 128 to 159 |
| 45 | 7.79 | 160 to 191 |
| 48 | 5.51 | 192 to 223 |
| 51 | 3.9 | 224 to 255 |

(*) control of the transmit gain by AT commands (for WISMO Quik Q24x6 Series driven by AT commands)

Microphone gain vs Max input voltage (using controller 2)

| Transmit Gain (dB) | Max Vin (mVrms) | AT+VGT |
|--------------------|-----------------|------------|
| - 6.5 | 3031 | 128 to 243 |
| -6.0 | 2861 | 224 |
| ... | ... | ... |
| 0.0 | 1434 | 0 |
| ... | ... | ... |
| +9.5 | 480 | 19 |
| +10.0 | 454 | 20 |
| | | |
| + 30.3 | 43.80 | 21 to 60 |
| + 30.8 | 41.36 | 61 |
| ... | ... | ... |
| + 50.8 | 4.14 | 101 |
| + 51.3 | 3.90 | 102 to 127 |

Recommended characteristics for the microphone:

- 2V – 0.5mA
- 2 KOhms
- Sensitivity -40 to -50dB
- SNR > 50dB
- Frequency response compatible with the GSM specifications

For possible references, see § 4.3.

2.12.1.2 Main Microphone Inputs (MIC2)

The MIC2 inputs are differential ones. They already include the convenient biasing for an electret microphone (0,5 mA and 2 Volts). This electret microphone can be directly connected on these inputs. The impedance of the microphone 2 has to be around 2kΩ. These inputs are standard ones for a handset design while MIC1 inputs can be connected to an external headset or a handsfree kit.

AC coupling is already embedded in the module.

Typical implementation:

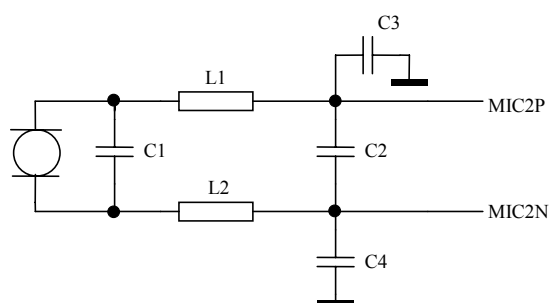


Figure 3 : MIC2 inputs (differential connection)

C1 = 10pF to 33pF

C2 = C3 = C4 = 47pF to 100pF

L1 = L2 = 100nH

C1 has to be the nearest possible to the microphone. Microphone manufacturers provide this capacitor directly soldered on the microphone.

C2 has to be very close to the WISMO Quik Q24x6 Series connector.

L1, L2, C3 and C4 has to be put near the WISMO Quik Q24x6 Series connector and can be removed according to their environment (ground plane, shielding, etc...). The best way is to plan all the components and to remove those which are not necessary to filter out the TDMA noise on the audio path.

Pin description

| Signal | Pin # | I/O | I/O type | Description |
|--------|-------|-----|----------|-----------------------------|
| MIC2P | 46 | I | Analog | Microphone 2 positive input |
| MIC2N | 48 | I | Analog | Microphone 2 negative input |

2.12.1.3 Auxiliary Microphone Inputs (MIC1)

The MIC1 inputs are differential and do not include internal bias. To use these inputs with an electret microphone, bias has to be generated outside the WISMO Quik Q24x6 Series module according to the characteristic of this electret microphone. These inputs are the standard ones used for an external headset or a handsfree kit.

AC coupling is already embedded in the module.

2.12.1.3.1 Differential connection

Impedance of the microphone input in differential mode :

- Module ON : $R_{in} = 10K\Omega \pm 10\%$
- Module OFF : $R_{in} > 1M\Omega \pm 10\%$

Typical implementation:

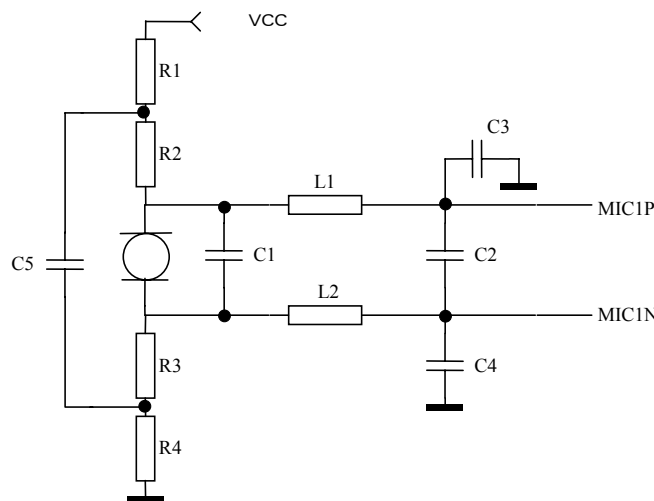


Figure 4 : MIC1 inputs (differential connection)

$R1 = R4 =$ from 100 to 330 Ω

$R2 = R3 =$ usually between 1K Ω and 3.3K Ω as per the microphone characteristics

$C1 =$ 10pF to 33pF

$C2 = C3 = C4 =$ 47pF to 100pF

$C5 =$ 47 μ F

$L1 = L2 =$ 100nH

R1 and R4 are used as a voltage supply filter with C5.

C1 has to be the nearest possible to the microphone. Microphone manufacturers provide this capacitor directly soldered on the microphone.

C2 has to be very close to the WISMO Quik Q24x6 Series connector.

L1, L2, C3 and C4 has to be put near the WISMO Quik Q24x6 Series connector and can be removed according to their environment (ground plane, shielding ...etc). The best way is to plan all the components and to remove those which are not necessary to filter out the TDMA noise on the audio path.

2.12.1.3.2 Single-ended connection

Typical implementation:

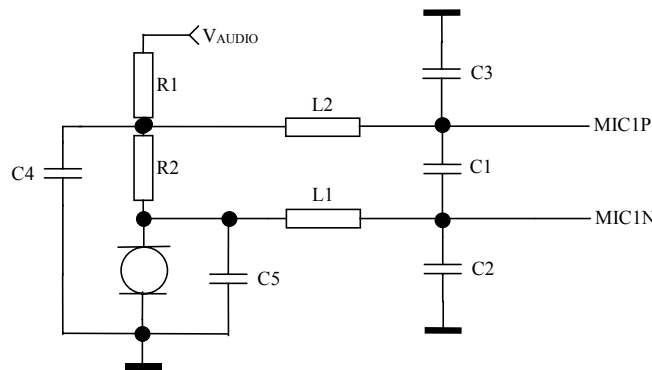


Figure 5 : MIC1 inputs (single-ended connection)

Note : V_AUDIO must be very "clean" in single-ended connection (for example, VCC plus filter cell like RC or LC).

R1 = from 100 to 330Ω

R2 = usually between 1KΩ and 3.3KΩ as per the V_AUDIO voltage level and the microphone characteristics

C1 = 10pF to 33pF

C2 = C3 = C5 = 47pF to 100pF

C4 = 47μF

L1 = L2 = 100nH

R1 is used as a voltage supply filter with C4.

C5 has to be the nearest possible to the microphone. Microphone manufacturers provide this capacitor directly soldered on the microphone.

C1, C2, C3 have to be very close to the WISMO Quik Q24x6 Series connector.

L1, and L2 has to be put near the WISMO Quik Q24x6 Series connector and can be removed according to their environment (ground plane, shielding ...etc). The best way is to plan all the components and to remove those which are not necessary to filter out the TDMA noise on the audio path.

Pin description

| Signal | Pin # | I/O | I/O type | Description |
|--------|-------|-----|----------|-----------------------------|
| MIC1P | 42 | I | Analog | Microphone 1 positive input |
| MIC1N | 44 | I | Analog | Microphone 1 negative input |

2.12.2 Common speaker outputs characteristics

The connection can be differential or single-ended but using a differential connection to reject common mode noise and TDMA noise is strongly recommended. Moreover in single-ended mode, 1/2 of the power is lost. When using a single-ended connection, be sure to have a very good ground plane, a very good filtering as well as shielding in order to avoid any disturbance on the audio path.

Speaker outputs SPK2 are push-pull amplifiers and can be loaded down to 150 Ohms and up to 1nF (see details in table *Speaker gain vs Max output voltage*). These outputs are differential and the output power can be adjusted by step of 2dB. The output can be directly connected to a speaker.

2.12.2.1 Differential Connection

Impedance of the speaker amplifier output in differential mode :

- $R \leq 1\Omega \pm 10\%$

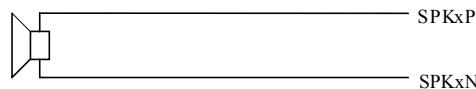


Figure 6 : SPK outputs (differential mode)

2.12.2.2 Single-ended Connection

Typical implementation:

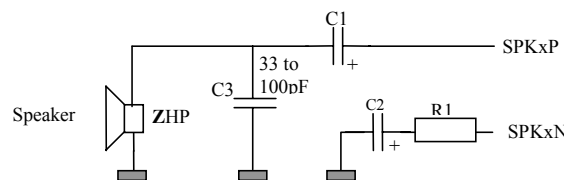


Figure 7 : SPK outputs (single-ended connection)

C1 = from 4.7µF to 47µF as per the speaker characteristics and the output power.

C1=C2 ; R1= Speaker Impedance

Using a single-ended connection also includes losing half of the output power compared to a differential connection.

Nevertheless in a 32 Ohms speaker case, you should use a cheaper and smaller solution : R1 = 82 Ohm et C2 = 4.7 μ F (ceramic)

The gain of SPK outputs is internally adjusted and can be tuned using an AT command.

Speaker gain vs Max output voltage

| Receive Gain (dB) (*) | Max output level (Vrms) | AT+VGR (**) | Max.speaker load (Ω) |
|-----------------------|-------------------------|-------------|-------------------------------|
| +2 | 1.74 | 0 to 15 | 150 |
| 0 | 1.38 | 16 to 31 | 50 |
| -2 | 1.099 | 32 to 47 | 32 |
| -4 | 0.873 | 48 to 63 | 32 |
| -6 | 0.693 | 64 to 79 | 32 |
| -8 | 0.551 | 80 to 95 | 32 |
| -10 | 0.437 | 96 to 111 | 32 |
| -12 | 0.347 | 112 to 127 | 32 |
| -14 | 0.276 | 128 to 143 | 32 |
| -16 | 0.219 | 144 to 159 | 32 |
| -18 | 0.174 | 160 to 175 | 32 |
| -20 | 0.138 | 176 to 191 | 32 |
| -22 | 0.110 | 192 to 207 | 32 |
| -24 | 0.087 | 208 to 223 | 32 |
| -26 | 0.069 | 224 to 239 | 32 |
| -26 | 0.069 | 240 to 255 | 32 |

(*) analog gain : might not be significant

(**) control of the receive gain by AT commands (for WISMO Quik Q24x6 Series driven by AT commands)

Recommended characteristics for the speaker:

- Type : 10 mW, electro-magnetic
- Impedance : 32 to 150 Ω
- Sensitivity : 110 dB SPL min. (0dB = 20 μ Pa)
- Frequency response compatible with the GSM specifications

For possible references, see chapter § 4.4.

2.12.3 Speaker outputs

2.12.3.1 Speaker 2 Outputs

Pin description

| Signal | Pin # | I/O | I/O type | Description |
|--------|-------|-----|----------|---------------------------|
| SPK2P | 45 | O | Analog | Speaker 2 positive output |
| SPK2N | 47 | O | Analog | Speaker 2 negative output |

2.12.3.2 Speaker 1 Outputs

Pin description

| Signal | Pin # | I/O | I/O type | Description |
|--------|-------|-----|----------|---------------------------|
| SPK1P | 41 | O | Analog | Speaker 1 positive output |
| SPK1N | 43 | O | Analog | Speaker 1 negative output |

2.12.4 Buzzer Output

The buzzer output is a digital one. A buzzer can be directly connected between this output and VBATT. The maximum current is 80 mA (PEAK). A diode against transient peak voltage must be connected as described below.

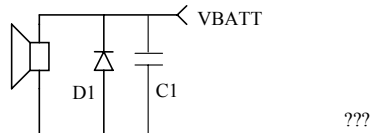


Figure 8 : Buzzer connection

R1 must be chosen in order to limit the current at I_{PEAK} max.

C1 = 0 to 100 nF (depending on the buzzer type).

Recommended characteristics for the buzzer :

- Type : electro-magnetic.
- Impedance : 7 to 30 Ω
- Sensitivity : 90 dB SPL min @ 10 cm

Pin description

| Signal | Pin # | I/O | I/O type | Description |
|--------|-------|-----|----------|---------------|
| BUZ | 49 | O | Analog | Buzzer output |

Operating conditions

| Parameter | Condition | Min | Max | Unit |
|---------------|--------------------|-----|-----|------|
| V_{OL} | $I_{moy} = 40mA$ | | 0.6 | v |
| I_{PEAK} | $VBATT = VBATTmax$ | | 80 | mA |
| $I_{AVERAGE}$ | $VBATT = VBATTmax$ | | 40 | mA |

2.13 Battery charging interface

The WISMO Quik Q24x6 Series module supports one battery charging circuit for Li-Ion batteries. This circuit uses an interface which consists of a current source inputs (CHG_IN) where the constant current has to flow in order to charge the battery. This current value depends on the battery capacity. It is recommended to provide a current equal to the value of the capacity plus 50mA. For a 550mA battery the current will be 600mA. The maximum current is 800mA.

A specific AT command (**AT+WBCM**), available from 4.3 level, allows to manage the charge battery (start and stop the charge, enable or disable unsolicited Battery Charge Indications and set the battery charge parameters).

The WISMO Quik Q24x6 Series module monitors the battery voltage to detect the end of the charge. WISMO Quik Q24x6 Series also monitors the temperature of the battery through the BAT_TEMP pin which has to be connected to a temperature sensor inside the battery (a NTC resistor for instance).

Pin description

| Signal | Pin number | I/O | I/O type | Description |
|----------|------------|-----|----------|----------------------|
| CHG_IN | 1, 2, 4 | I | Analog | Current source input |
| BAT_TEMP | 38 | I | Analog | A/D converter |

Electrical Characteristics

| Parameter | Min | Max | Typ | Unit |
|--|------|-----|-----|--------|
| BAT_TEMP resolution | 10 | | | bits |
| BAT_TEMP sampling rate | 90.3 | | | Ksps/s |
| BAT_TEMP Input Impedance (R) | 4.7 | | | kΩ |
| BAT_TEMP Input Impedance (C) | | 100 | | nF |
| CHG_IN Voltage (for I=I _{max}) | 5,1* | 5,5 | | V |
| CHG_IN Current | | 800 | | mA |
| BAT_TEMP Input signal range | | | 2.8 | V |

* To be parametrized as per battery manufacturer

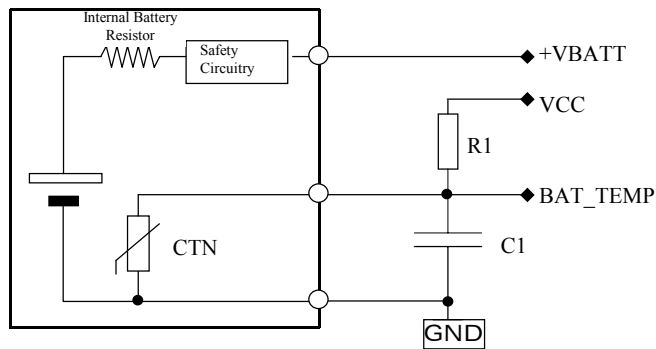


Figure 9 : Connection examples

2.13.1 Li-ion charging procedure

A constant current source has to be provided through **CHG_IN** input in order to charge the Li-ion battery, and **BAT_TEMP** input has to be connected to a battery temperature sensor. During this procedure the voltage of the battery is accurately monitored.

The Li-ion charging involves two phases. During the first phase, the battery is charged with a constant current until its voltage reaches 4.1V*. During the second phase the constant current is pulsed by the module. The width and the frequency of the pulse change during this phase in order to ensure a safety charge. The battery is considered as fully charged when, after a pulse, the voltage remains at a 4.1V* during more than 10s.

The Li-ion battery must have an included safety circuit to avoid any discharge or overcharge. This circuit is delivered by the manufacturer inside the battery pack. The impedance of this safety circuit has to be the lowest possible in order to reduce the drop-out of the voltage. This drop-out is due to the RF Power Amplifier current (up to 2.0A). A maximum of 150mΩ is required.

(*) : To be parametrized as per battery manufacturer

2.13.2 How to define R1 and C1

How to choose R1

R1 has to be chosen to have a full range of BAT-TEMP (from 0V to 2.8V) when the CTN value changes from the minimum to the maximum temperature

How to choose C1

C1 has to be chosen to have a RC filter with a time constant lower than 2ms.

Calculation examples

$$CTN(25^{\circ}C) = 47K$$

$$CTN(55^{\circ}C) = 10K$$

$$CTN(-10^{\circ}C) = 300K$$

$$CTN(-10^{\circ}C) \times VCC = (CTN(-10^{\circ}C) + R1) \times BAT-TEMP (full range)$$

$$R1 = 47K \Rightarrow BAT-TEMP(-20^{\circ}C) = 2.42V$$

$$BAT-TEMP(55^{\circ}C) = 0.49V$$

$$R(-20^{\circ}C) = R1 // CTN(-10^{\circ}C) = 40K$$

$$R(+55^{\circ}C) = 8K$$

With C= 10nF ::

$$RC(-20^{\circ}C) = 400\mu s$$

$$RC(+55^{\circ}C) = 80\mu s$$

2.14 ON / ~OFF

This input is used to switch ON or OFF the WISMO Quik Q24x6 Series module. A high level signal has to be provided on the pin ON/~OFF to switch ON the module. The level of the voltage of this signal has to be maintained between 2.4V and VDD during a minimum of 1000ms. This signal can be left at high level until switch off.

To be able to switch OFF the module, the pin ON/OFF has to be released. Through the firmware, the module can be switched off (using the CPOF command).

Pin description

| Signal | Pin number | I/O | I/O type | Description |
|---------|------------|-----|----------|-----------------|
| ON/~OFF | 6 | I | CMOS | Module Power ON |

Electrical Characteristics

| Parameter | Min | Max | Unit |
|-----------------------|-----|-----|------------|
| Input Impedance (R) | 10 | | k Ω |
| Input Impedance (C) | | 50 | pF |

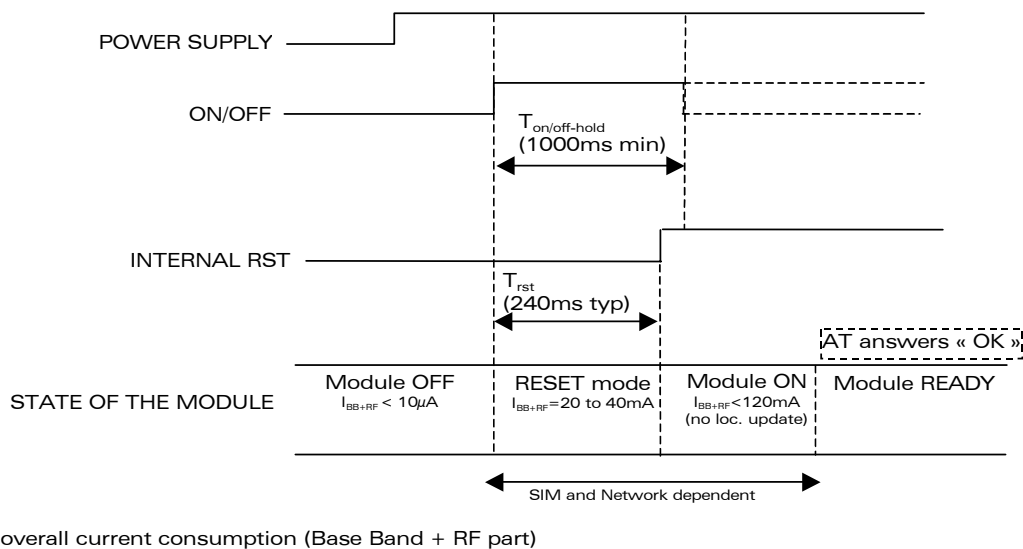
Operating conditions

| Parameter | I/O type | Min | Max | Unit |
|-----------------|----------|-------|----------|------|
| V _{IL} | | 0 V | 0.6 V | V |
| V _{IH} | | 2.4 V | VDD+0.5V | V |

2.14.1 Operating sequences

2.14.1.1 Power ON

Once the module supplied, the application must set the ON/OFF signal to high to start the module power ON sequence. The ON/OFF signal must be hold for 1000ms minimum. After this time, an internal mechanism keeps it on hold. During the power ON sequence, an internal reset is automatically performed by the module for 240ms (typical). During this phase, any external reset should be avoided. Once the initialisation is complete (timing is SIM and network dependent) the AT interface answers « OK » to the application³. For further details, please check the AT commands manual (+WIND, +WAIP)



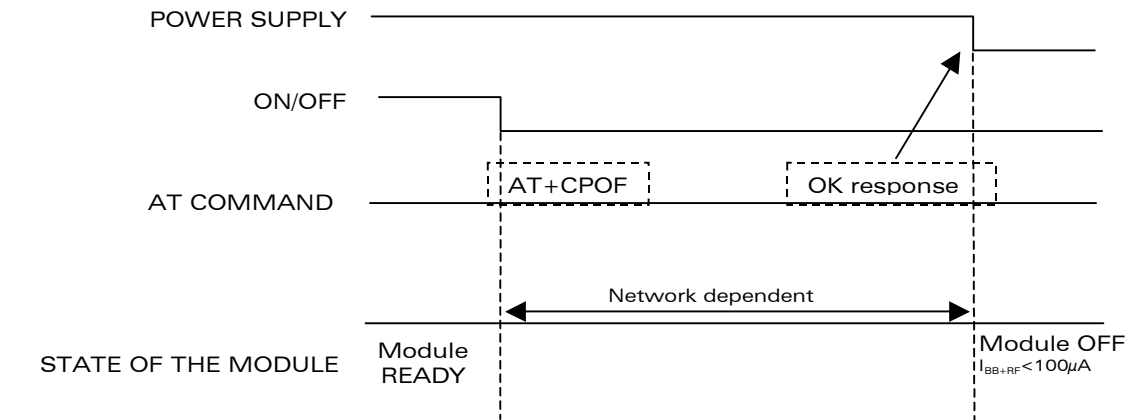
I_{BB+RF} = overall current consumption (Base Band + RF part)

Figure 10 : Power-ON sequence (no PIN code activated)

³ For this, the application has to send AT.J. If the application manages hardware flow control, the AT command can be sent during the initialisation phase. Another solution is to use the +WIND command to get an unsolicited status from the module.

2.14.1.2 Power OFF

To properly power OFF the module, the application must set the ON/OFF signal to low and then send the AT+CPOF command to de-register from the network and switch off the module. Once the « OK » response is issued by the module, the power supply can be switched off.



I_{BB+RF} = overall current consumption (Base Band + RF part)

Figure 11 : Power-OFF sequence

2.15 BOOT (optional)

This input can be used to download a software in the Flash ROM of the WISMO Quik Q24x6 Series module. For the applications based on AT commands this is a backup download procedure only (see chapter Firmware upgrade). The internal boot procedure is started when this pin is low during the reset of the module. In normal mode this pin has to be left open. In Internal boot mode, low level has to be set through a 1KΩ resistor. If used, this input has to be driven by an open collector or an open drain.

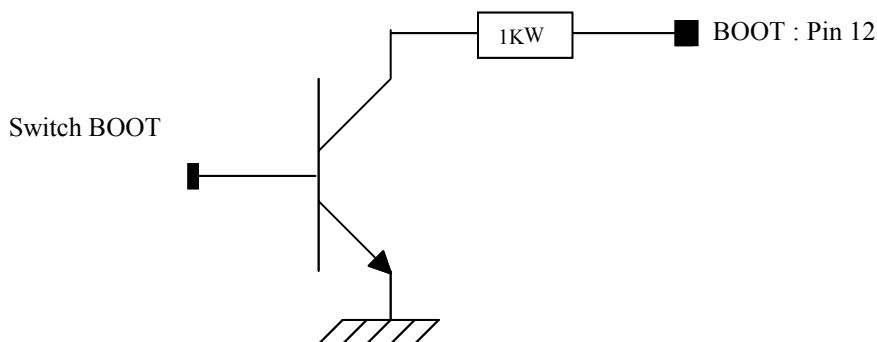


Figure 12 : BOOT pin connection

- If Switch Boot = 1, Boot pin 12 = 0, for download mode
- If Switch Boot = 0, Boot pin 12 = 1, for normal mode

Pin description

| Signal | Pin number | I/O | I/O type | Description |
|--------|------------|-----|----------|---------------|
| BOOT | 12 | I | CMOS | Flash Loading |

Note : The nominal firmware download procedure is using the X-modem

2.16 Reset signal (~RST)

This signal is used to force a reset procedure by providing low level during at least 500µs. This signal has to be considered as an emergency reset only. A reset procedure is already driven by an internal hardware during the power-up sequence.

This signal can also be used to provide a reset to an external device. It then behaves as an output. If no external reset is necessary this input can be left open. If used (emergency reset), it has to be driven by an open collector or an open drain.

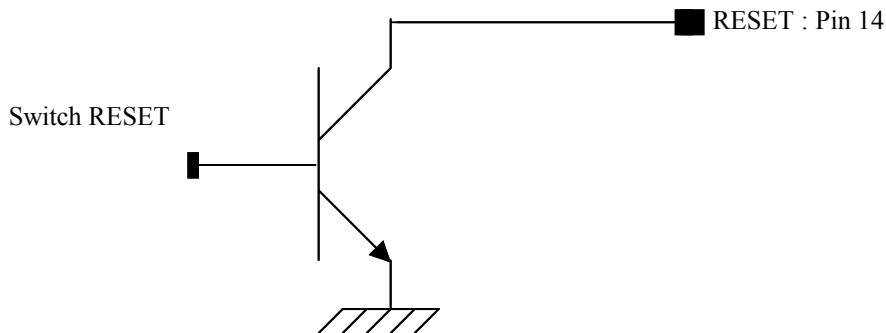


Figure 13 : RST pin connection

- If Switch Reset = 1, Reset pin 14 = 0, for Module Reset
- If Switch Reset = 0, Reset pin 14 = 1, for normal mode

Pin description

| Signal | Pin number | I/O | I/O type | Description |
|--------|------------|-----|----------|--------------|
| ~RST | 14 | I/O | | Module Reset |

Electrical Characteristics

| Parameter | Min | Max | Unit |
|-----------------------|-----|-----|------|
| Input Impedance (R) | 4.7 | | kΩ |
| Input Impedance (C) | | 10 | nF |

Operating conditions

| Parameter | Min | Max | Condition |
|------------------|-------|-------|--------------------------|
| *V _{T-} | 1.1V | 1.2 V | |
| *V _{T+} | 1.7V | 1.9 V | |
| V _{OL} | | 0.4 V | I _{OL} = -50 μA |
| V _{OH} | 2.0 V | | I _{OH} = 50 μA |

* V_{T-}, V_{T+}: Hysterisis Level

Additional comments on RESET:

The RESET process is activated either by the external ~RST signal OR by an internal signal (coming from a RESET generator). This automatic reset is activated at Power-up.

The module remains in reset mode as long as the RST signal is held low. This signal should be used only for "emergency" resets.

A software reset will be preferred to a HW reset.

2.16.1 Reset sequence

To activate the « emergency » reset sequence, the ~RST signal has to be set to low for 500µs minimum. As soon as the reset is complete, the AT interface answers « OK » to the application⁴.

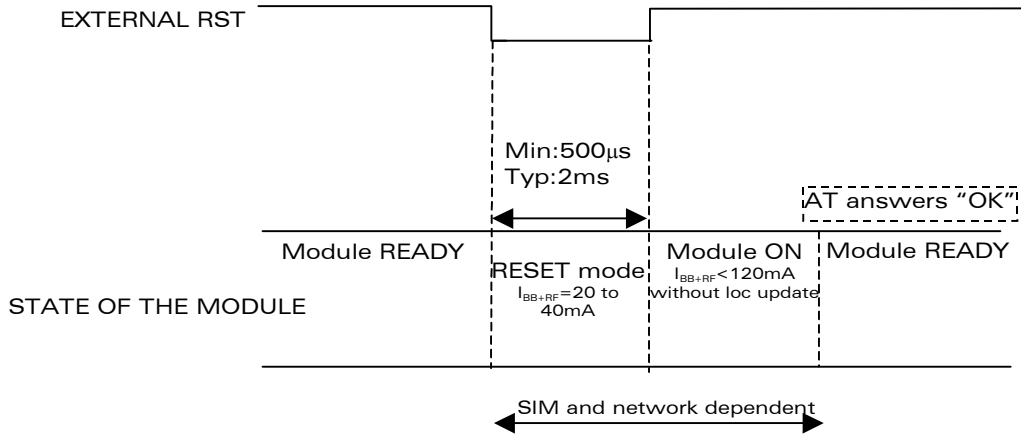


Figure 14 : Reset sequence

2.17 External Interrupt (~INTR)

The WISMO Quik Q24x6 Series provides an external interrupt input (not managed in the standard AT commands firmware). This input is very sensitive and an interrupt is activated on high to low edge. If this signal is not used it can be left open. If used this input has to be driven by an open collector or an open drain.

This input is used for instance to power OFF automatically the module.

Pin description

| Signal | Pin number | I/O | I/O type | Description |
|--------|------------|-----|----------|--------------------|
| ~INTR | 16 | I | CMOS | External Interrupt |

Electrical characteristics

| Parameter | Min | Max | Unit |
|-----------------|-------|------|------|
| V _{IL} | -0.5V | 0.7V | Volt |
| V _{IH} | 2.2V | 3.0V | Volt |

⁴ For this, the application has to send AT.J. If the application manages hardware flow control, the AT command can be sent during the initialisation phase. Another solution is to use the +WIND command to get an unsolicited status from the module.

2.18 VCC output

This output can be used to power some external functions. **VCC** has to be used as a digital power supply. This power supply is available when the module is on.

Pin description

| Signal | Pin number | I/O | I/O type | Description |
|--------|------------|-----|----------|----------------|
| VCC | 40 | O | Supply | Digital supply |

Operating conditions

| Parameter | Condition | Min | Max | Unit |
|----------------|-----------|------|------|------|
| Output voltage | I = 10mA | 2.74 | 2.86 | V |
| Output Current | | | 10 | mA |

2.19 VCC_RTC (Real Time Clock Supply)

2.19.1 Interface description

This pin is used as a back-up power supply for the internal Real Time Clock. The RTC is supported by the module when powered on but a back-up power supply is needed to save date and hour when the module is switched off.

If the RTC is not used this pin can be left open.

Pin description

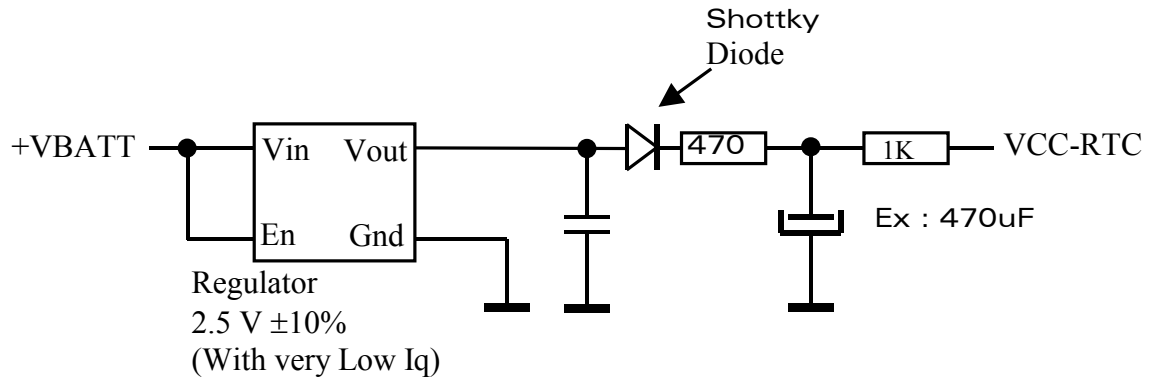
| Signal | Pin number | I/O | I/O type | Description |
|---------|------------|-----|----------|--------------------|
| VCC_RTC | 56 | I/O | Supply | RTC Back-up supply |

Operating conditions

| Parameter | Condition | Min | Max | Unit |
|----------------|---|-----|------|------|
| Input voltage | | 2 | 2.75 | V |
| Input Current | VCC=0V; t° = 25°C VCC_RTC=2.5V | | 3 | μA |
| Input Current | VCC=0V; t°:-20°C / 55°C VCC_RTC=2.5V | | 10 | μA |
| Output voltage | | 2.4 | 2.75 | V |
| Output current | | | 2 | mA |

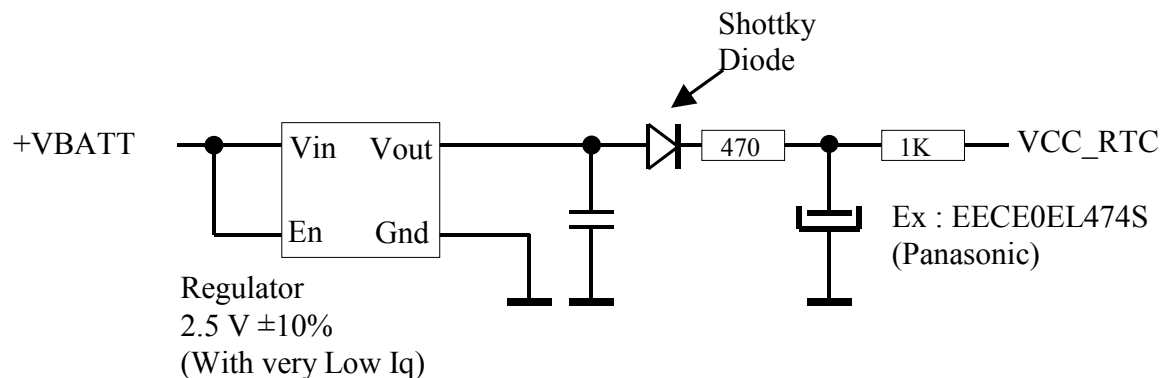
2.19.2 Typical implementation

2.19.2.1 Capacitor



Estimated range with 470 μ F Capacitor : ~30 seconds.

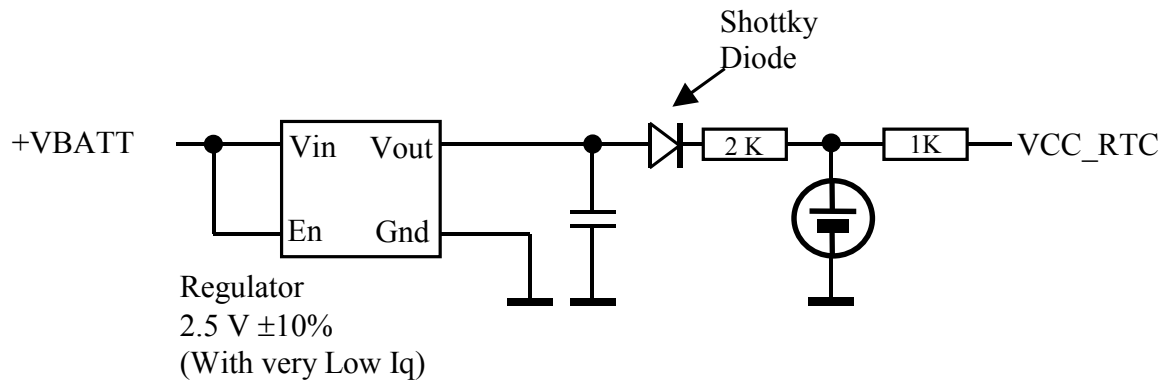
2.19.2.2 Super Capacitor



Estimated range with 0.47 Farad Gold Cap : 2 hours min.

Note : the Gold Capacitor maximum voltage is 2.5 V.

2.19.2.3 Battery cell with regulator



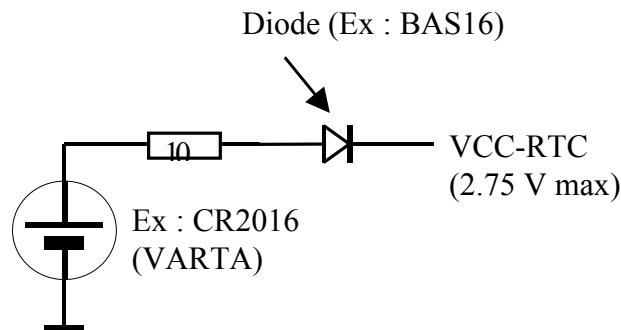
Estimated range with 2 mAh battery rechargeable battery : ~3 days.

Warning :

Before battery cell assembly insure that cell voltage is lower than 2,75V to avoid any damage to the WISMO module.

2.19.2.4 Non Rechargeable battery

This is the less recommended solution.



Estimated range with 85 mAh battery : 4000 h minimum

Note : The "non rechargeable battery" is always active, except when the module is ON.

2.20 RF interface

The impedance is 50 Ohms nominal and the DC impedance is 0 Ohm.

2.20.1 RF connections

Spring contact

Two land patterns set on the PCB support the RF connection which can be used by the application through spring contacts or a soldered RF cable.

Since no standard spring contact is available for WISMO Quik Q24x6 Series, this solution requires a specific part to be developed.

Soldered solution

The soldered solution will preferably be based on a RG178 coaxial cable.

Notes :

- The WISMO Quik Q24x6 Series does not support an antenna switch for a car kit but this function can be implemented externally and it can be driven using a GPIO.
- The antenna cable and connector should be chosen in order to minimise losses in the frequency bands used for GSM 850/900MHz and 1800/1900MHz.
- 0.5dB can be considered as a maximum value for loss between the module and an external connector.

2.20.2 RF performances

RF performances are compliant with the ETSI recommendation GSM 05.05.

The main parameters for Receiver are :

- GSM850 Reference Sensitivity (Q2426) = -104 dBm Static & TUHigh
- E-GSM900 Reference Sensitivity (Q2406) = -104 dBm Static & TUHigh
- DCS1800 Reference Sensitivity (Q2406) = -102 dBm Static & TUHigh
- PCS1900 Reference Sensitivity (Q2426) = -102 dBm Static & TUHigh
- Selectivity @ 200 kHz : > +9 dBc
- Selectivity @ 400 kHz : > +41 dBc
- Linear dynamic range : 63 dB
- Co-channel rejection : >= 9 dBc

And for Transmitter :

- Maximum output power (EGSM & GSM850): 33 dBm +/- 2 dB at ambient temperature
- Maximum output power (GSM1800 & PCS1900) : 30 dBm +/- 2 dB at ambient temperature
- Minimum output power (EGSM & GSM850) : 5 dBm +/- 5 dB at ambient temperature
- Minimum output power (GSM1800 & PCS1900) : 0 dBm +/- 5 dB at ambient temperature

2.20.3 Antenna specifications

The antenna must fulfil the following requirements :

- Frequency depends on application. A dualBand antenna shall work in these frequency bands and have the following characteristics :

| Characteristic | Q2406 | | Q2426 | |
|-----------------------|--------------------------------|------------------|----------------|------------------|
| | E-GSM 900 | DCS 1800 | GSM 850 | PCS 1900 |
| Frequency TX | 880 to 915 MHz | 1710 to 1785 MHz | 824 to 849 MHz | 1850 to 1910 MHz |
| Frequency RX | 925 to 960 MHz | 1805 to 1880 MHz | 869 to 894 MHz | 1930 to 1990 MHz |
| Impedance | 50 Ohms | | | |
| VSWR | Rx max | 1.5 :1 | | |
| | Tx max | 1.5 :1 | | |
| Typical radiated gain | 0dBi in one direction at least | | | |

3 Technical specifications

3.1 General Purpose Connector pin out description

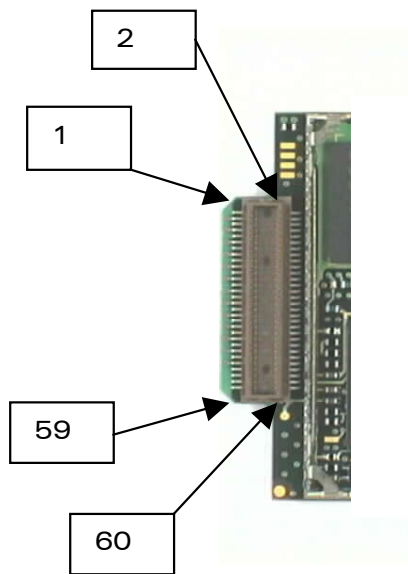
| Pin # | Name | I/O | I/O type | Description | Comment |
|-------|---------------------|-----|------------|--|--|
| 1 | CHG_IN | I | Supply | Supply for battery charging | High current |
| 2 | CHG_IN | I | Supply | Supply for battery charging | High current |
| 3 | SIMCLK | O | 2 X | Clock for SIM interface | |
| 4 | CHG_IN | I | Supply | Supply for battery charging | High current |
| 5 | SIMRST | O | 2 X | Reset for SIM interface | |
| 6 | ON/~OFF | I | CMOS | Power ON/OFF control | |
| 7 | SIMDATA | I/O | CMOS / 3X | I/O for SIM interface | |
| 8 | SDA/SPI_IO | I/O | CMOS/1X | Wire interface or SPI Data | |
| 9 | SIMVCC | O | Supply | SIM card supply | 6mA max |
| 10 | SCL/SPI_CLK | O | 1X | Wire interface or SPI clock | |
| 11 | VDD | I | Supply | Low power supply | 3.1V minimum or connected to VBATT |
| 12 | BOOT | I | CMOS | BOOT | Pull down through 1K for Flash downloading |
| 13 | ROW0 | I/O | CMOS/1X | Keyboard Row | |
| 14 | ~RST | I/O | SCHMITT | Module Reset | Active low |
| 15 | ROW1 | I/O | CMOS/1X | Keyboard Row | |
| 16 | ~INTR | I | CMOS | External interrupt | Active low. 100K Pull-up inside |
| 17 | ROW2 | I/O | CMOS/1X | Keyboard Row | |
| 18 | GPI or CT103/TXD2 * | I | CMOS or 3x | General Purpose Input or Aux.serial Link | 100K Pull-down inside - Multiplexed |

| Pin # | Name | I/O | I/O type | Description | Comment |
|-------|-----------------------|-----|-----------------|--|---|
| 19 | ROW3 | I/O | CMOS/1X | Keyboard Row | |
| 20 | GPO2 or XT104/RXD2 * | O | 1X or CMOS | General Purpose Output or Aux.serial Link | Multiplexed |
| 21 | ROW4 | I/O | CMOS/1X | Keyboard Row | |
| 22 | GPO1 | I/O | 3X | General Purpose Output | |
| 23 | COL0 | I/O | CMOS/1X | Keyboard Column | |
| 24 | GPIO0 or CT106/CTS2 * | I/O | CMOS/2X or CMOS | General Purpose I/O or Aux. serial Link | Multiplexed |
| 25 | COL1 | I/O | CMOS/1X | Keyboard Column | |
| 26 | GPO0 or SPI_AUX | O | 3X | General Purpose Output or SPI Aux SIM 3V / 5V | Multiplexed |
| 27 | COL2 | I/O | CMOS/1X | Keyboard Column | |
| 28 | SPI_EN or GPO3 | O | 1X | SPI enable or General Purpose Output | Multiplexed |
| 29 | COL3 | I/O | CMOS/1X | Keyboard Column | |
| 30 | CT105/RTS1 | I | CMOS | RS232 interface Request To Send | Pull up to VCC with 100K Ω when not used |
| 31 | COL4 | I/O | CMOS/1X | Keyboard Column | |
| 32 | CT104/RXD1 | O | 1X | RS232 interface - Receive | |
| 33 | AUXV0 | I | Analog | Auxiliar ADC input 0 | Can be tied to GND if not used |
| 34 | CT108-2/DTR1 | I | CMOS | RS232 interface Data Terminal Ready | Pull up to VCC with 100K Ω when not used |
| 35 | GPIO5 or CT105/RTS2 * | I/O | CMOS / 2X or 2x | General Purpose I/O or Aux. serial Link | Multiplexed |
| 36 | CT107/DSR1 | O | 1X | RS232 interface Data Set Ready | |
| 37 | CT106/CTS1 | O | 1X | RS232 interface Clear To Send | |

| Pin # | Name | I/O | I/O type | Description | Comment |
|-------|-------------------------|----------|----------|--|--|
| 38 | BAT_TEMP | I | Analog | ADC input for battery temperature measurement | Can be tied to GND if not used |
| 39 | CT103/TXD1 | I | CMOS | RS232 interface - Transmit | Pull up to VCC with 100 K Ω when not used |
| 40 | VCC | O | Supply | 2.8V digital supply output | 10mA max. |
| 41 | SPK1P | O | Analog | Speaker 1 positive output | |
| 42 | MIC1P | I | Analog | Microphone 1 positive input | |
| 43 | SPK1N | O | Analog | Speaker 1 negative output | |
| 44 | MIC1N | I | Analog | Microphone 1 negative input | |
| 45 | SPK2P | O | Analog | Speaker 2 positive output | |
| 46 | MIC2P | I | Analog | Microphone 2 positive input | |
| 47 | SPK2N | O | Analog | Speaker 2 negative output | |
| 48 | MIC2N | I | Analog | Microphone 2 negative input | |
| 49 | BUZ | O | Analog | Buzzer output | 80mA max |
| 50 | SIMPRES | I | CMOS | SIM Card Detect | |
| 51 | GPIO3 or CT109/DCD1 | I/O O | CMOS/2X | General Purpose I/O RS232 - Data Carrier Detect | Multiplexed |
| 52 | GPIO1 FLASH LED | I/O | CMOS/2X | General Purpose I/O Module State | Multiplexed |
| 53 | GPIO4 | I/O | CMOS/2X | General Purpose I/O | |
| 54 | GPIO2 or CT125 / RI1 | I/O O | CMOS/2X | General Purpose I/O RS232 - Ring Indicator | Multiplexed |
| 55 | +VBATT | | Supply | Battery Input | High current |

| Pin # | Name | I/O | I/O type | Description | Comment |
|-------|---------|-----|----------|--------------------|--------------|
| 56 | VCC_RTC | I/O | Supply | RTC back-up supply | |
| 57 | +VBATT | | Supply | Battery Input | High current |
| 58 | +VBATT | | Supply | Battery Input | High current |
| 59 | +VBATT | | Supply | Battery Input | High current |
| 60 | +VBATT | | Supply | Battery Input | High current |

* Auxiliary Serial link not available on Q24x6D and Q24x6E products



WISMO Quik Q24x6 series pin position (bottom view)

3.2 Environmental Specifications

| Conditions | Temperature range |
|---|-------------------|
| Operating / Full GSM specifications compliant | -20°C to +55°C |
| Storage | -30°C to +85°C |

| WISMO 2D10/Q24x6 | | ENVIRONNEMENTAL CLASSES | | |
|-------------------------------|---------------------------|---|---|--|
| TYPE OF TEST | STANDARDS | STORAGE Class 1.2 | TRANSPORTATION Class 2.3 | OPERATING (PORT USE) Class 7.3 |
| Cold | IEC 68-2.1 Ab test | -25° C 72 h | -40° C 72 h | -20° C (GSM900) 16 h -10° C (GSM1800/1900) 16h |
| Dry heat | IEC 68-2.2 Bb test | +70° C 72 h | +70° C 72 h | +55° C 16 h |
| Change of temperature | IEC 68-2.14 Na/Nb test | | -40° / +30° C 5 cycles t1 = 3 h | -20° / +30° C (GSM900) 3 cycles -10° / +30° C (GSM1800/1900): 3 cycles t1 = 3 h |
| Damp heat cyclic | IEC 68-2.30 Db test | +30° C 2 cycles 90% - 100% RH variant 1 | +40° C 2 cycles 90% - 100% RH variant 1 | +40° C 2 cycles 90% - 100% RH variant 1 |
| Damp heat | IEC 68-2.56 Cb test | +30° C 4 days | +40° C 4 days | +40° C 4 days |
| Sinusoidal vibration | IEC 68-2.6 Fc test | 5 - 62 Hz : 5 mm / s 62 - 200Hz : 2 m / s2 3 x 5 sweep cycles | | |
| Random vibration wide band | IEC 68-3.36 Fdb test | | 5 - 20 Hz : 0.96 m2 / s3 20 - 500Hz : - 3 dB / oct 3 x 10 min | 10 -12 Hz : 0.96 m2 / s3 12 - 150Hz : - 3 dB / oct 3 x 30 min |

3.3 Mechanical specifications

3.3.1 Physical characteristics

The WISMO Quik Q24x6 Series module has a complete self-contained shield.

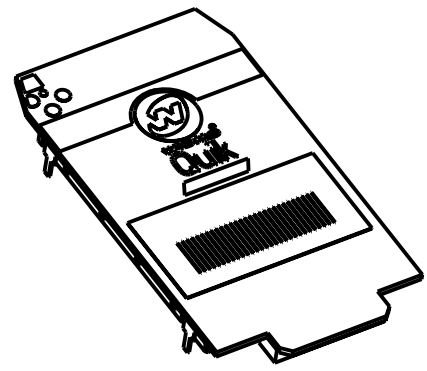
- Dimensions : 58.4 x 32.2 x 3.9 mm external dimensions (except shielding pins)
- Weight : <12 g

3.3.2 Mechanical drawings

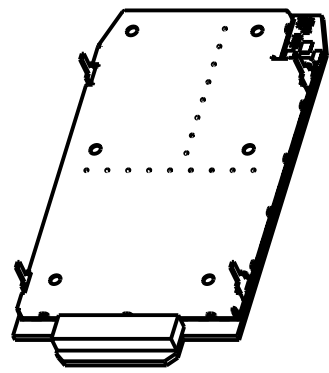
The next page gives the mechanical specifications of WISMO Quik Q24x6 Series.

MAXIMUM BULK OCCUPIED ON THE MOTHER BOARD

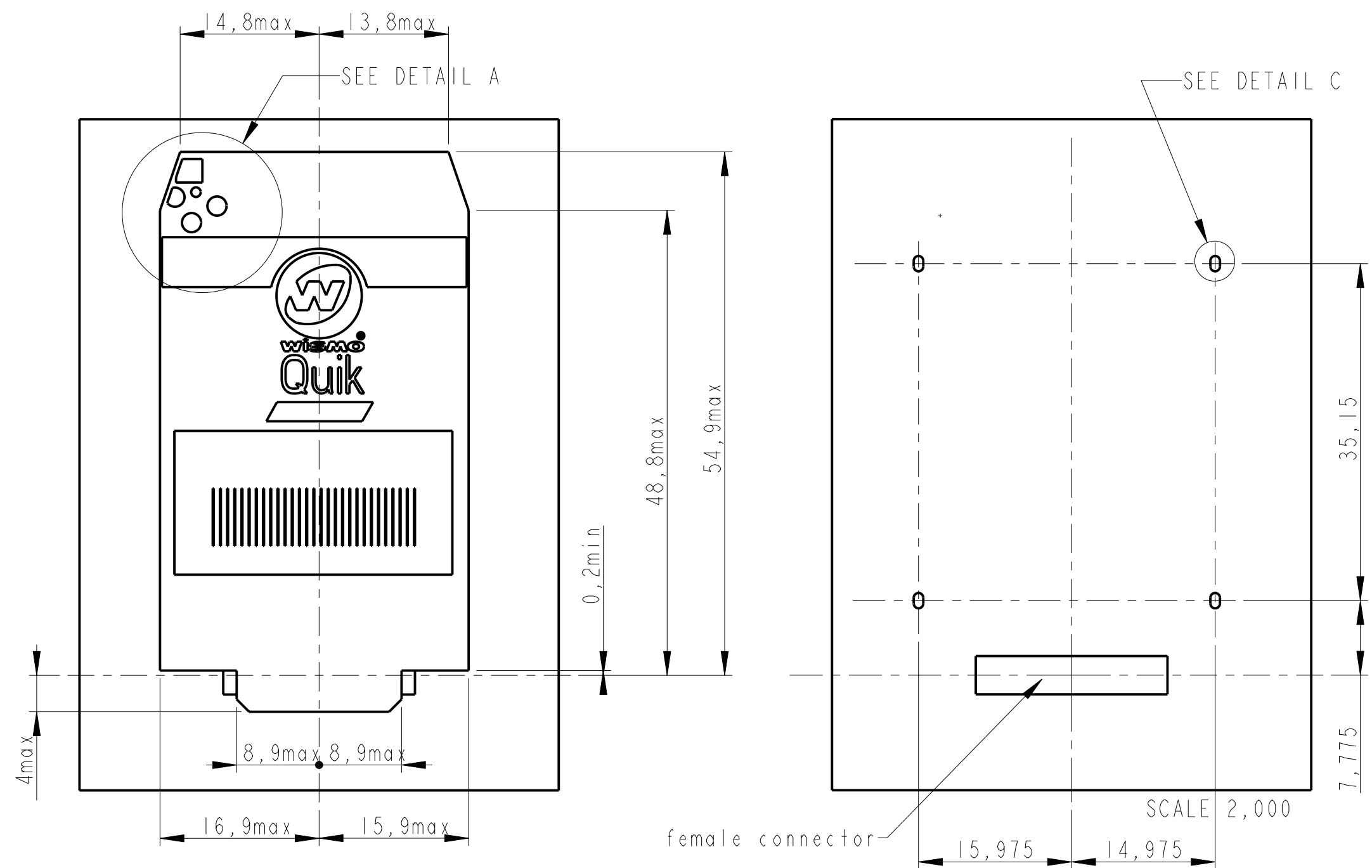
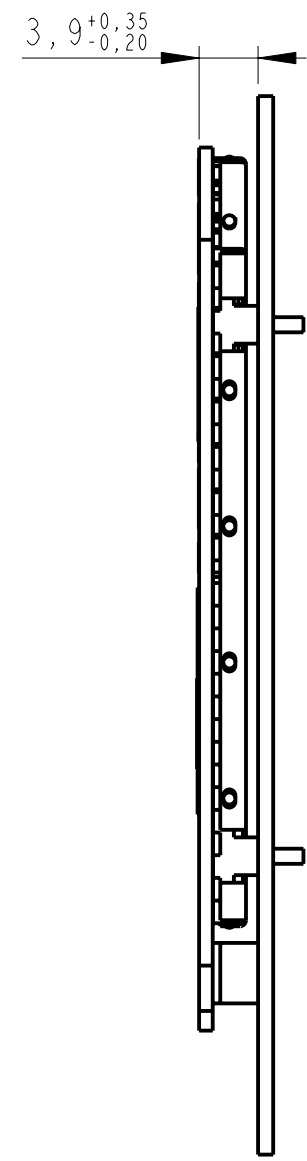
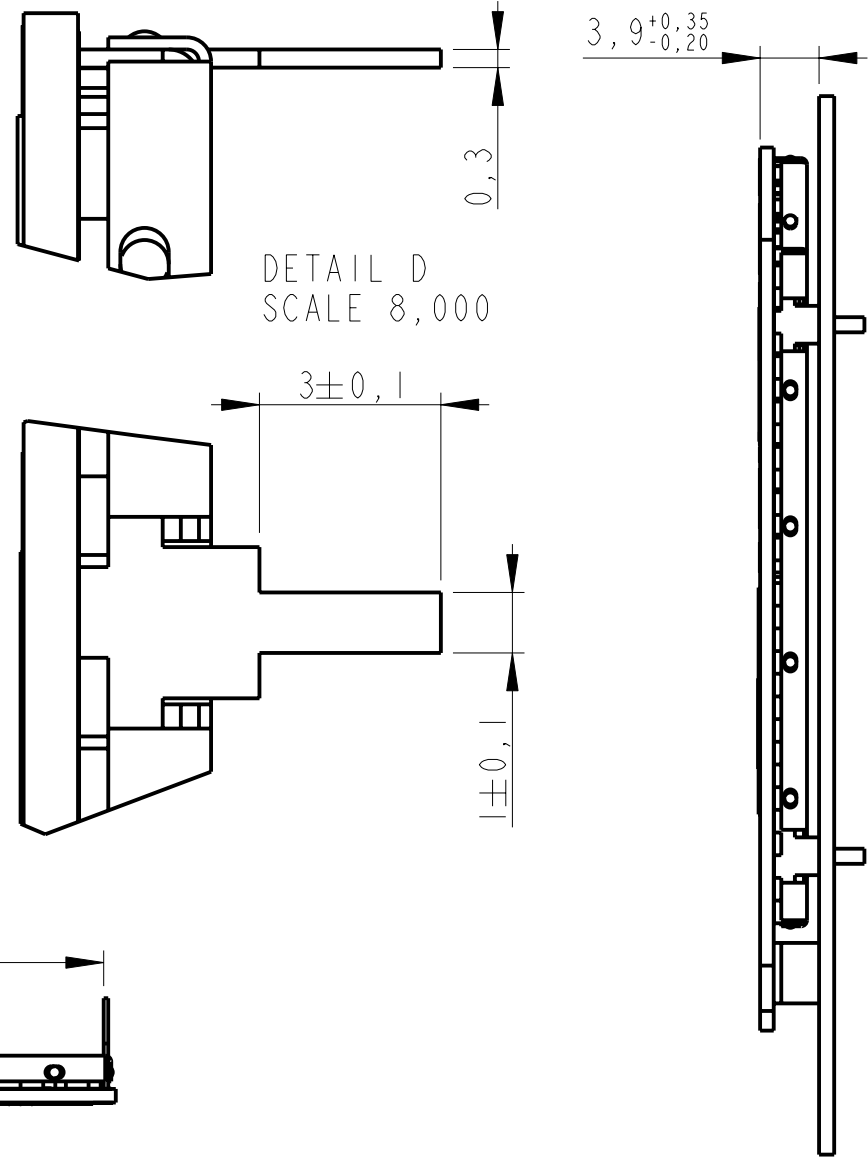
SCALE 1,000



SCALE 1,000

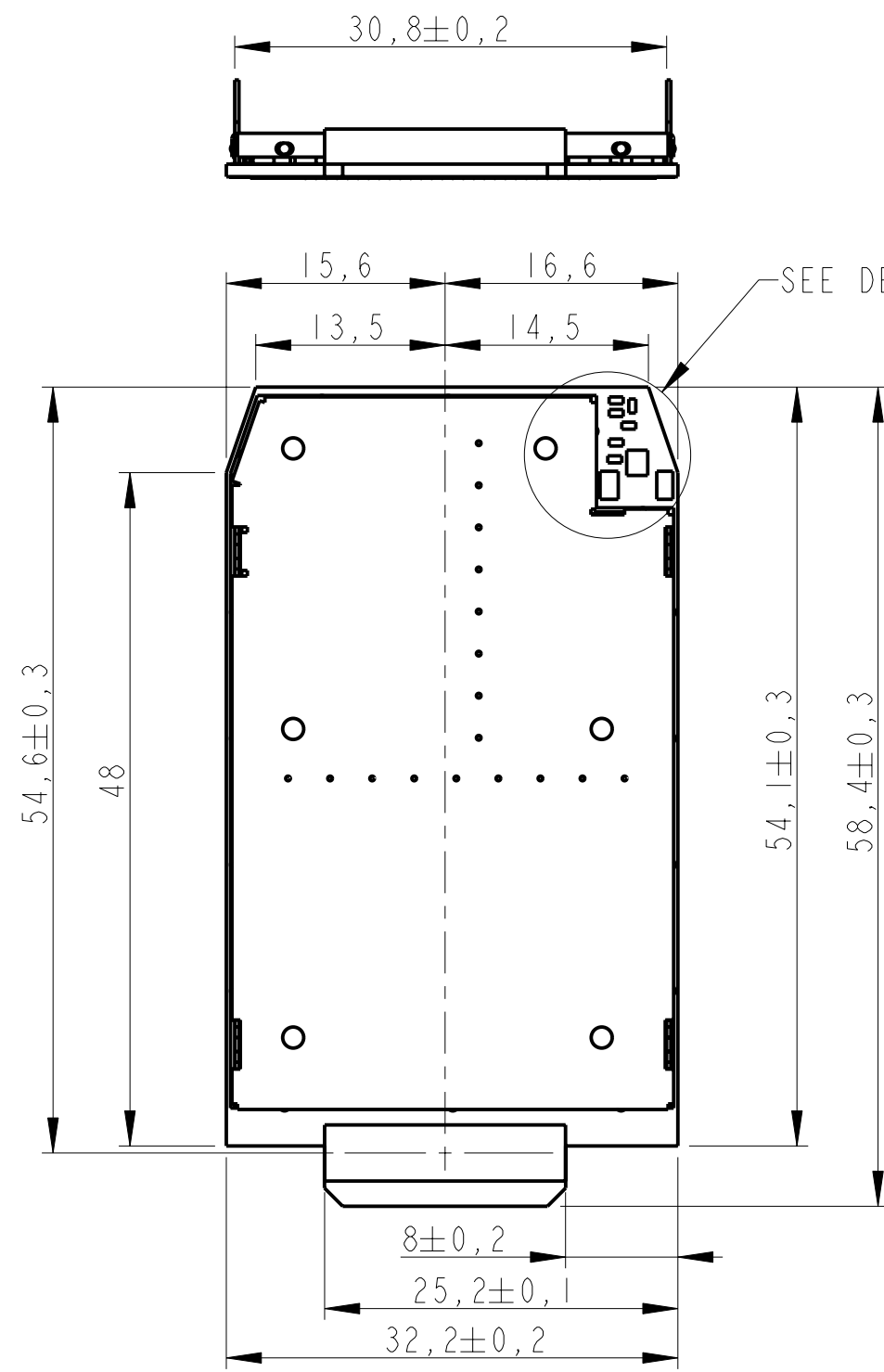


DETAIL D
SCALE 8,000

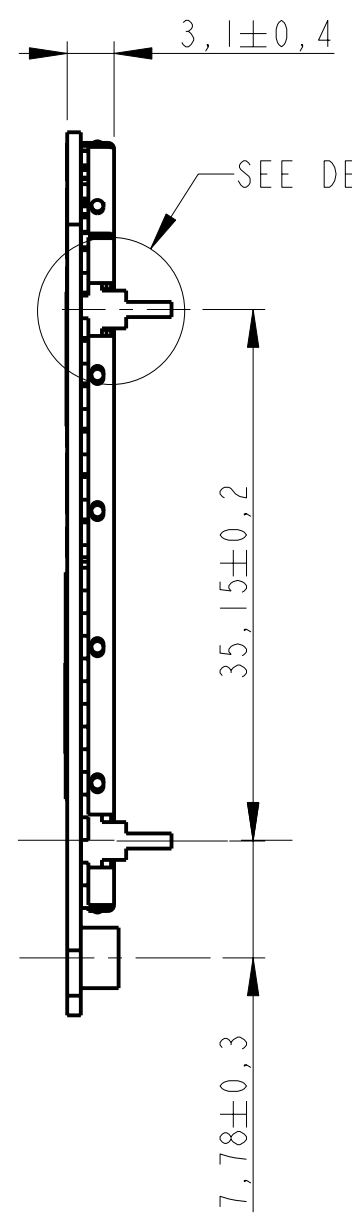


SCALE 2,000

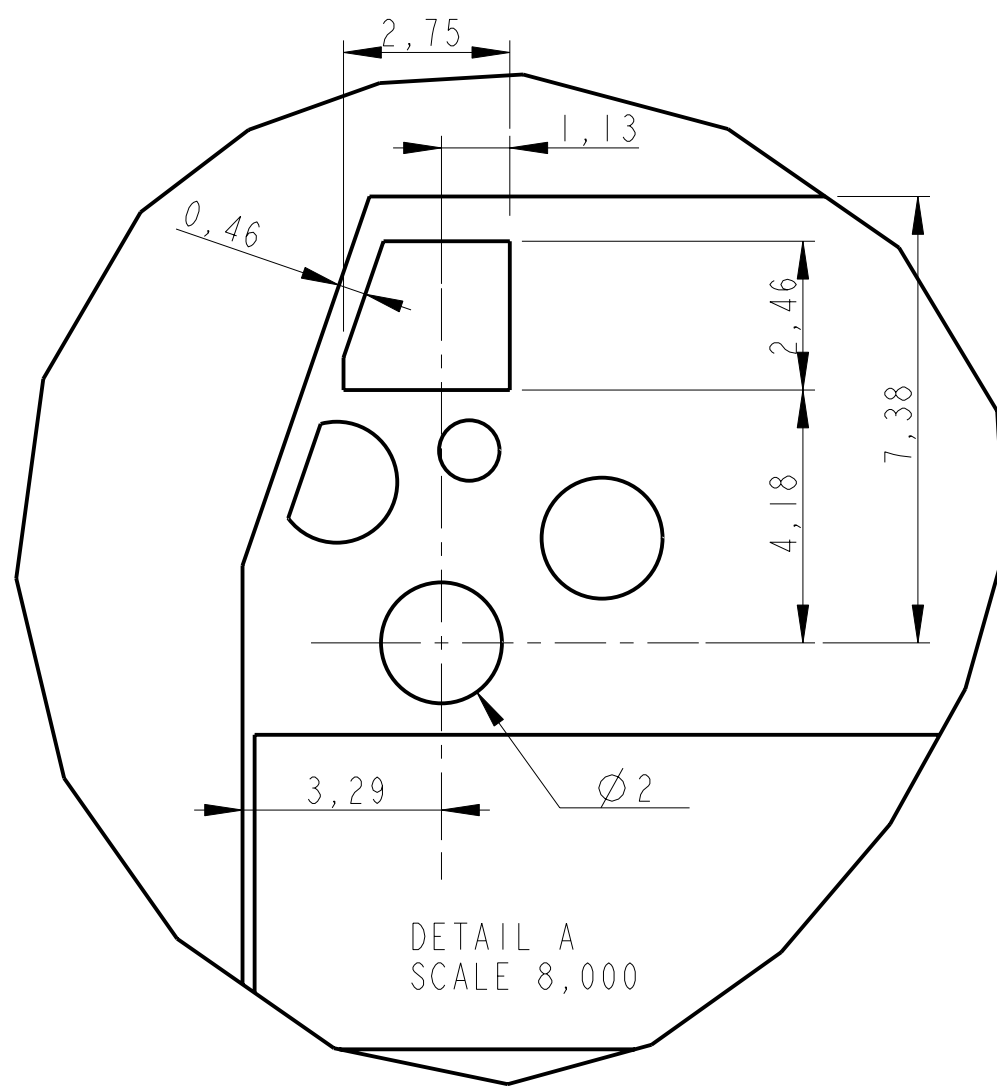
female connector



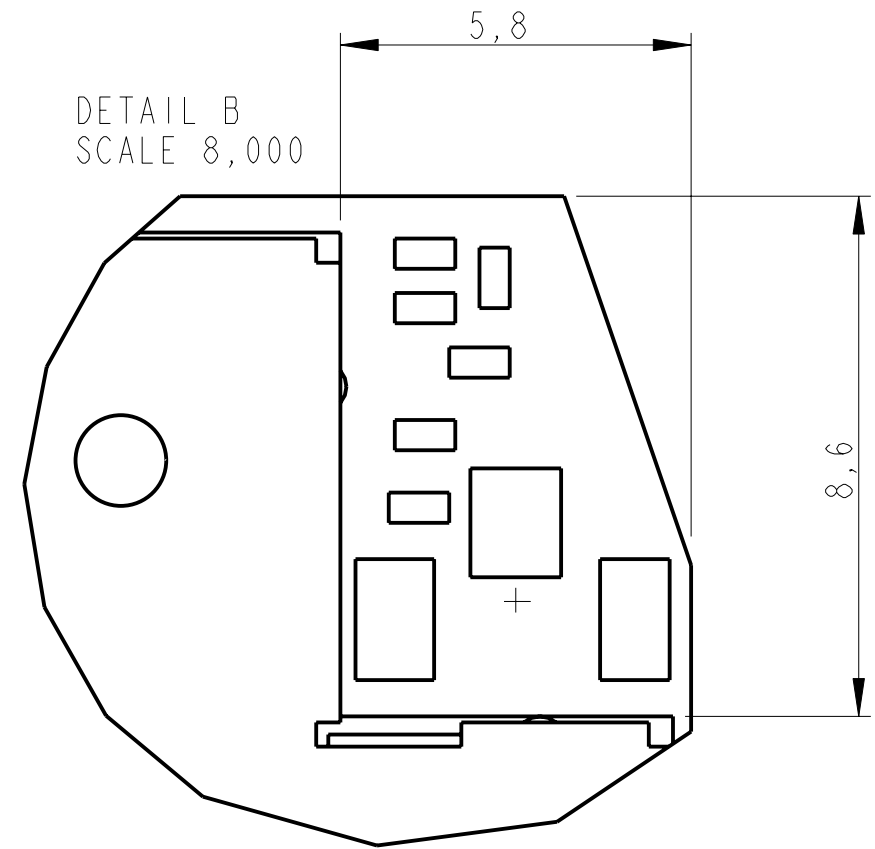
SEE DETAIL B



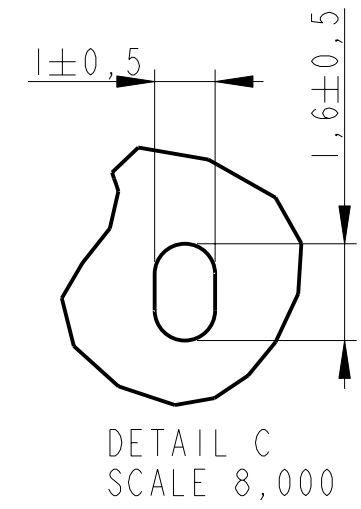
SEE DETAIL D



DETAIL A
SCALE 8,000



DETAIL B
SCALE 8,000



DETAIL C
SCALE 8,000

| | | | | | |
|-----------------|----------|--------|-------|------------|-----|
| Modif. matching | 18/11/02 | JPM | JJO | Prototypes | 02 |
| Creation | 23/10/02 | JPM | JJO | Prototypes | 01 |
| MODIFICATION | DATE | AUTHOR | RESP. | STATUS | IND |

| | | | |
|-------------------|-------------------|-------------------|-------------|
| Wismo 2D10 | | TOL.GEN.: ±0,2 | SCALE 2,000 |
| MODULE DIMENSIONS | | FOLIO: 1/1 | FORMAT: A2 |
| wavecom | | WM-2-2171-V-001-A | |
| | | AUTEUR: JPM | 02 |
| | | RESPONS: JJO | |
| PRO/ENGINEER | WM2D10_DIMENSIONS | IND. | |

4 Connectors and peripheral devices references

4.1 General Purpose Connector

The GPC is a 60 pins connector with 0.5mm pitch from KYOCERA / AVX group with the following reference :

14 5087 060 930 861.

The matting connector has the following reference :

24 5087 060 X00 861⁵.

The stacking height is 3.0 mm.

For further details see GPC data sheets in appendix. More information is also available from <http://www.avxcorp.com>

4.2 SIM Card Reader

- ITT CANNON CCM03 series (see <http://www.ittcannon.com>)
- AMPHENOL C707 series (see <http://www.amphenol.com>)
- JAE (see <http://www.jae.com>)

Drawer type :

- MOLEX 99228-0002 (connector) / MOLEX 91236-0002 (holder) (see <http://www.molex.com>)

4.3 Microphone

Possible suppliers :

- HOSIDEN
- PANASONIC

⁵ X=2 or 9

4.4 Speaker

Possible suppliers :

- SANYO
- HOSIDEN
- PRIMO
- PHILIPS

4.5 Antenna Cable

The following cable reference has been qualified for being mounted on WISMO Quik Q24x6 Series :

- RG178

4.6 GSM antenna

GSM antennas and support for antenna adaptation can be obtained from manufacturers such as:

- ALLGON (<http://www.allgon.com>)
- MOTECO (<http://www.moteco.com>)
- GALTRONICS (<http://www.galtronics.com>)

5 Design Guidelines

The purpose of the following paragraphs is to give design guidelines.

5.1 HARDWARE and RF

5.1.1 EMC recommendations

The EMC tests have to be performed as soon as possible on the application to detect any possible problem.

When designing, special attention should be paid to:

- Possible spurious emission radiated by the application to the RF receiver in the receiver band
- ESD protection on SIM (if accessible from outside), serial link,...
- EMC protection on audio input/output (filters against 900MHz emissions)
- Bias of the Microphone inputs
- Length of the SIM interface lines (preferably <10cm)
- Ground plane : WAVECOM recommends to have a common ground plane for analog / digital / RF grounds.
- Metallic case or plastic casing with conductive paint are recommended

Note :

The module does not include any protection against overvoltage.

5.1.2 Power Supply

The power supply is one of the key issues in the design of a GSM terminal.

A weak power supply design could affect in particular :

- EMC performances
- the emissions spectrum
- the phase error and frequency error

Warning:

Careful attention should be paid to :

- Quality of the power supply : low ripple, PFM or PSM systems should be avoided (PWM converter preferred).
- Capacity to deliver high current peaks in a short time (pulsed radio emission).

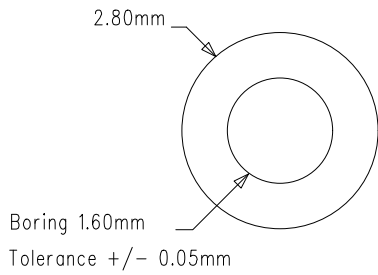
5.1.3 Layout requirement

CHIPS & BORING DIAMETER

of the WISMO QUIK mechanical insertion pins

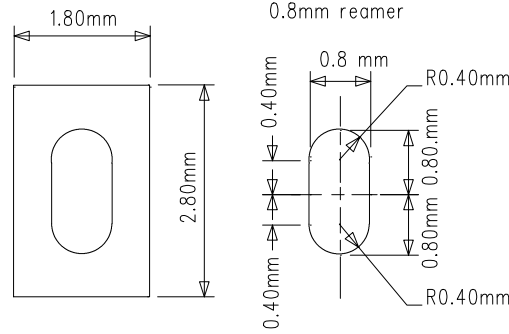
CASE N 1

To be used in priority



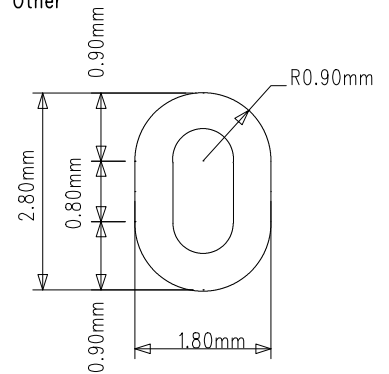
CASE N 2

on specific request



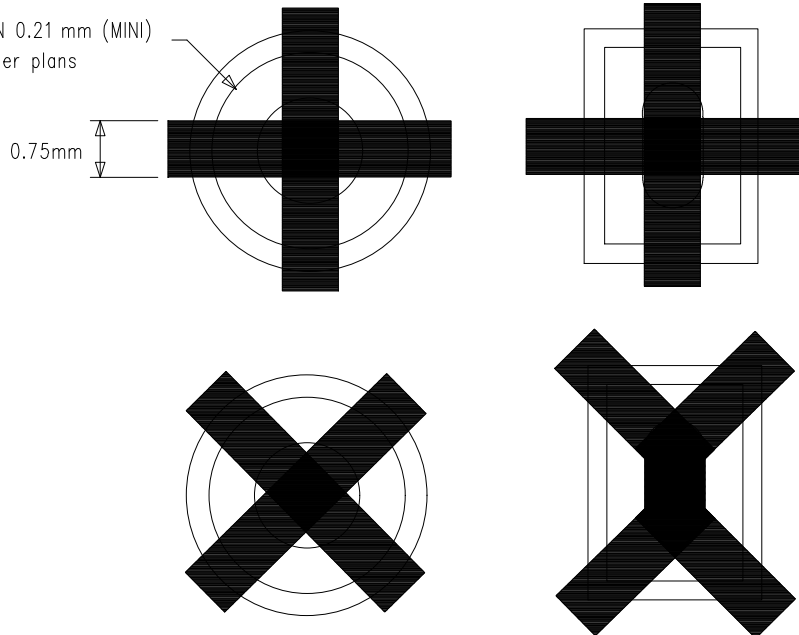
CASE N 3

Other



THERMAL BRAKES DEFINITION

ISOLATION 0.21 mm (MINI)
with copper plans



NORMALISATION INDUSTRIELLE

ETABLI : HER

DATE : 03/04/02

APPROUVE : DPL

SECTION : 1545

WAVECOM

CHIPS & BORING DIAMETER
OF THE WISMO QUIK
MECHANICAL INSERTION PINS

5.1.4 Antenna

Warning:

Wavecom strongly recommends to work with an antenna manufacturer either to develop an antenna adapted to the application or to adapt an existing solution to the application. The antenna adaptation (mechanical and electrical adaptation) is one of the key issues in the design of a GSM terminal.

5.2 Mechanical integration

Attention should be paid to :

- Antenna cable integration (bending, length, position, etc)
- Legs of the module to be soldered on the Ground plane

5.3 Firmware upgrade

The WISMO Quik Q24x6 Series firmware is stored in flash memory and it can easily be upgraded.

In order to follow the regular evolutions of the GPRS standard and to offer state of the art software, Wavecom recommends that the application designed around a WISMO (or WISMO based product) allows easy firmware upgrades on the module via the standard Xmodem protocol. Therefore, the application shall either allow a direct access to the WISMO serial link through an external connector or implement any mechanism allowing the WISMO firmware to be downloaded via Xmodem.

Two upgrade procedures are available:

5.3.1 Nominal upgrade procedure

The firmware file can be downloaded into the modem using the Xmodem protocol.

To enter this mode, the AT+WDWL command (see description in the AT command manual) has to be sent.

The necessary serial signals to proceed with the Xmodem downloading are:

Rx, Tx, RTS, CTS and GND.

5.3.2 Backup procedure

In case the nominal upgrade mode is not possible (due to critical corruption on the flash memory), a backup procedure is also available. It requires a WAVECOM specific software to download the firmware file into the modem.

This tool has to run on a PC connected to the serial bus of the modem.

The necessary signals to proceed with the downloading are: Rx, Tx, RTS, CTS and GND.

Prior to running the WAVECOM downloader, the modem has to be set in download mode.

For this, the BOOT signal has to be set to low while powering ON (or resetting) the modem.

Advise : To reduce the time of the download, it's possible to change the speed of the serial link at 115200 bits/s. for that, you have to execute the AT command below :

- 1) AT+IPR=115200
- 2) AT+WDWL
- 3) file transfer
- 4) AT+CFUN=1 (reset of the module)

Make attention that after the last command, the serial link will be by default at 9600 bits/s.

6 Appendix

6.1 Wavecom acceptance test

These tests are Wavecom internal qualification tests. They are performed on a Wavecom evaluation platform (module on test board).

| Test | Applied standard | Acceptance criteria |
|------------------|--|---|
| Performance Test | Mobile Station (MS) conformance specification; Part 1: Conformance specification (Release 5). 3GPP TS 51.010 v5.0.0 (2002-09) | Full conformity to the recommendation regarding the main RF parameters. |
| Cooking Test | - | The test continues even after the Cooking Test milestone has been reached |
| Stress Test | Therma shocks IEC 68-2-14. | Full conformity to the recommendation regarding the main parameters. |
| Vibration Test | Sinusoidal vibration IEC 68-2-6. | No performance degradation or mechanical degradation is allowed after test. |
| Vibration Test | Random vibration IEC 68-2-36. | No performance degradation or mechanical degradation is allowed after test. |
| Shock Test | IEC 68-2-27. | No performance degradation or mechanical degradation is allowed after test. |
| Bump Test | IEC 68-2-29. | No performance degradation or mechanical degradation is allowed after test. |
| Humidity Test | Corrosion test IEC 68-2-3. | No visible degradation of the product, both visual and fonctionnal. The unit is tested at room temperature and must be fully operative for the main RF parameters. |
| Warehouse Test | Low temperance IEC 68-2-1. | Under normal condition (room temperature) after the test, the unit must behave in full conformity with the main RF parameters specification. |
| Warehouse Test | High temperature IEC 68-2-2. | Under normal condition (room temperature) after the test, the unit must behave in full conformity with the main RF parameters specification. |
| Dust Test1 | MIL-STD-810D, method 510-3. | No visible dust in the visible areas. No more than 50 dust particules in the cabinet of the product. The unit, tested at room temperature must be fully operative. |
| Light Test1 | UV radiation and temperature EDF HN60E03. | Visual inspection on the discoloration and other degradation effects such as cracks in the material of the unit after the test. |
| Fall Test1 | IEC 68-2-32. | Only minor casing degradation is allowed, with a maximum dimension change of 1mm. The unit must remain fully operative and full specification for the main RF parameters. |

| Test | Applied standard | Acceptance criteria |
|-------------------------------|--|--|
| Electro Static Discharge Test | IEC 1000-4-2 or EN 61000-4-2 / A1 Edition 1998 / A2 Edition 2001 | No performance degradation allowed after the test. |
| Salt Mist Test | IEC 68-2-11 | After the test, visual inspection on the unit. |
| Atmosphere Test | Flowing mixed gas corrosion. IEC 68-2-60 | After the test, visual inspection on the unit and inside. |
| Marking Test | EN 60950:2000 (Safety tests standard) | After the test, visual inspection on the unit. No degradation is allowed on the marking. |

6.2 Standards and Recommendations

GSM ETSI, 3GPP, GCF and NAPRD03 recommendations for Phase II.

| Specification Reference | Title |
|---|---|
| 3GPP TS 45.005 v5.5.0 (2002-08) Release 5 | Technical Specification Group GSM/EDGE. Radio Access Network; Radio transmission and reception |
| GSM 02.07 V8.0.0 (1999-07) | Digital cellular telecommunications system (Phase 2+); Mobile Stations (MS) features (GSM 02.07 version 8.0.0 Release 1999) |
| GSM 02.60 V8.1.0 (1999-07) | Digital cellular telecommunications system (Phase 2+); General Packet Radio Service (GPRS); Service description, Stage 1 (GSM 02.60 version 8.1.0 Release 1999) |
| GSM 03.60 V7.9.0 (2002-09) | Technical Specification Group Services and System Aspects; Digital cellular telecommunications system (Phase 2+); General Packet Radio Service (GPRS); Service description; Stage 2 (Release 1998) |
| 3GPP TS 43.064 V5.0.0 (2002-04) | Technical Specification Group GERAN; Digital cellular telecommunications system (Phase 2+); General Packet Radio Service (GPRS); Overall description of the GPRS radio interface; Stage 2 (Release 5) |
| 3GPP TS 03.22 V8.7.0 (2002-08) | Technical Specification Group GSM/EDGE. Radio Access Network; Functions related to Mobile Station (MS) in idle mode and group receive mode; (Release 1999) |
| 3GPP TS 03.40 V7.5.0 (2001-12) | Technical Specification Group Terminals; Technical realization of the Short Message Service (SMS) (Release 1998) |
| 3GPP TS 03.41 V7.4.0 (2000-09) | Technical Specification Group Terminals; Technical realization of Cell Broadcast Service (CBS) (Release 1998) |
| ETSI EN 300 903 V8.1.1 (2000-11) | Digital cellular telecommunications system (Phase 2+); Transmission planning aspects of the speech service in the GSM Public Land Mobile Network (PLMN) system (GSM 03.50 version 8.1.1 Release 1999) |

| Specification Reference | Title |
|------------------------------------|---|
| 3GPP TS 04.06 V8.2.1 (2002-05) | Technical Specification Group GSM/EDGE Radio Access Network; Mobile Station - Base Station System (MS - BSS) interface; Data Link (DL) layer specification (Release 1999) |
| 3GPP TS 04.08 V7.18.0 (2002-09) | Technical Specification Group Core Network; Digital cellular telecommunications system (Phase 2+); Mobile radio interface layer 3 specification (Release 1998) |
| 3GPP TS 04.10 V7.1.0 (2001-12) | Technical Specification Group Core Networks; Mobile radio interface layer 3 Supplementary services specification; General aspects (Release 1998) |
| 3GPP TS 04.11 V7.1.0 (2000-09) | Technical Specification Group Core Network; Digital cellular telecommunications system (Phase 2+); Point-to-Point (PP) Short Message Service (SMS) support on mobile radio interface (Release 1998) |
| 3GPP TS 45.005 v5.5.0 (2002-08) | Technical Specification Group GSM/EDGE. Radio Access Network; Radio transmission and reception (Release 5) |
| 3GPP TS 45.008 V5.8.0 (2002-08) | Technical Specification Group GSM/EDGE Radio Access Network; Radio subsystem link control (Release 5) |
| 3GPP TS 45.010 V5.1.0 (2002-08) | Technical Specification Group GSM/EDGE Radio Access Network; Radio subsystem synchronization (Release 5) |
| 3GPP TS 46.010 V5.0.0 (2002-06) | Technical Specification Group Services and System Aspects; Full rate speech; Transcoding (Release 5) |
| 3GPP TS 46.011 V5.0.0 (2002-06) | Technical Specification Group Services and System Aspects; Full rate speech; Substitution and muting of lost frames for full rate speech channels (Release 5) |
| 3GPP TS 46.012 V5.0.0 (2002-06) | Technical Specification Group Services and System Aspects; Full rate speech; Comfort noise aspect for full rate speech traffic channels (Release 5) |

| Specification Reference | Title |
|-----------------------------------|--|
| 3GPP TS 46.031 V5.0.0 (2002-06) | Technical Specification Group Services and System Aspects; Full rate speech; Discontinuous Transmission (DTX) for full rate speech traffic channels (Release 5) |
| 3GPP TS 46.032 V5.0.0 (2002-06) | Technical Specification Group Services and System Aspects; Full rate speech; Voice Activity Detector (VAD) for full rate speech traffic channels (Release 5) |
| TS 100 913V8.0.0 (1999-08) | Digital cellular telecommunications system (Phase 2+); General on Terminal Adaptation Functions (TAF) for Mobile Stations (MS) (GSM 07.01 version 8.0.0 Release 1999) |
| GSM 09.07 V8.0.0 (1999-08) | Digital cellular telecommunications system (Phase 2+); General requirements on interworking between the Public Land Mobile Network (PLMN) and the Integrated Services Digital Network (ISDN) or Public Switched Telephone Network (PSTN) (GSM 09.07 version 8.0.0 Release 1999) |
| 3GPP TS 51.010-1 v5.0.0 (2002-09) | Technical Specification Group GSM/EDGE ; Radio Access Network ;Digital cellular telecommunications system (Phase 2+);Mobile Station (MS) conformance specification; Part 1: Conformance specification (Release 5) |
| 3GPP TS 51.011 V5.0.0 (2001-12) | Technical Specification Group Terminals; Specification of the Subscriber Identity Module - Mobile Equipment (SIM - ME) interface (Release 5) |
| ETS 300 641 (1998-03) | Digital cellular telecommunications system (Phase 2); Specification of the 3 Volt Subscriber Identity Module - Mobile Equipment (SIM-ME) interface (GSM 11.12 version 4.3.1) |
| GCF-CC V3.7.1 (2002-08) | Global Certification Forum – Certification criteria |
| NAPRD03 V2.6.0 (2002-06) | North America Permanent Reference Document for PTCRB tests |

6.3 Safety recommendations (for information only)

IMPORTANT

FOR THE EFFICIENT AND SAFE OPERATION OF YOUR GSM APPLICATION BASED ON WISMO Quik Q24x6 Series PLEASE READ THIS INFORMATION CAREFULLY

6.3.1 RF safety

6.3.1.1 General

Your GSM terminal⁶ is based on the GSM standard for cellular technology. The GSM standard is spread all over the world. It covers Europe, Asia and some parts of America and Africa. This is the most used telecommunication standard.

Your GSM terminal is actually a low power radio transmitter and receiver. It sends out and receives radio frequency energy. When you use your GSM application, the cellular system which handles your calls controls both the radio frequency and the power level of your cellular modem.

6.3.1.2 Exposure to RF energy

There has been some public concern about possible health effects of using GSM terminals. Although research on health effects from RF energy has focused on the current RF technology for many years, scientists have begun research regarding newer radio technologies, such as GSM. After existing research had been reviewed, and after compliance to all applicable safety standards had been tested, it has been concluded that the product was fitted for use.

If you are concerned about exposure to RF energy there are things you can do to minimize exposure. Obviously, limiting the duration of your calls will reduce your exposure to RF energy. In addition, you can reduce RF exposure by operating your cellular terminal efficiently by following the below guidelines.

6.3.1.3 Efficient terminal operation

For your GSM terminal to operate at the lowest power level, consistent with satisfactory call quality :

If your terminal has an extendible antenna, extend it fully. Some models allow you to place a call with the antenna retracted. However your GSM terminal operates more efficiently with the antenna fully extended.

Do not hold the antenna when the terminal is « IN USE ». Holding the antenna affects call quality and may cause the modem to operate at a higher power level than needed.

⁶ based on WISMO2D

6.3.1.4 Antenna care and replacement

Do not use the GSM terminal with a damaged antenna. If a damaged antenna comes into contact with the skin, a minor burn may result. Replace a damaged antenna immediately. Consult your manual to see if you may change the antenna yourself. If so, use only a manufacturer-approved antenna. Otherwise, have your antenna repaired by a qualified technician.

Use only the supplied or approved antenna. Unauthorized antennas, modifications or attachments could damage the terminal and may contravene local RF emission regulations or invalidate type approval.

6.3.2 General safety

6.3.2.1 Driving

Check the laws and the regulations regarding the use of cellular devices in the area where you have to drive as you always have to comply with them. When using your GSM terminal while driving, please :

- give full attention to driving,
- pull off the road and park before making or answering a call if driving conditions so require.

6.3.2.2 Electronic devices

Most electronic equipment, for example in hospitals and motor vehicles is shielded from RF energy. However RF energy may affect some improperly shielded electronic equipment.

6.3.2.3 Vehicle electronic equipment

Check your vehicle manufacturer representative to determine if any on-board electronic equipment is adequately shielded from RF energy.

6.3.2.4 Medical electronic equipment

Consult the manufacturer of any personal medical devices (such as pacemakers, hearing aids, etc...) to determine if they are adequately shielded from external RF energy.

Turn your terminal **OFF** in health care facilities when any regulations posted in the area instruct you to do so. Hospitals or health care facilities may be using RF monitoring equipment.

6.3.2.5 Aircraft

Turn your terminal OFF before boarding any aircraft.

- Use it on the ground only with crew permission.
- Do not use it in the air.

To prevent possible interference with aircraft systems, Federal Aviation Administration (FAA) regulations require you to have permission from a crew member to use your terminal while the aircraft is on the ground. To prevent interference with cellular systems, local RF regulations prohibit using your modem while airborne.

6.3.2.6 Children

Do not allow children to play with your GSM terminal. It is not a toy. Children could hurt themselves or others (by poking themselves or others in the eye with the antenna, for example). Children could damage the modem, or make calls that increase your modem bills.

6.3.2.7 Blasting areas

To avoid interfering with blasting operations, turn your unit OFF when in a « blasting area » or in areas posted : « turn off two-way radio ». Construction crew often use remote control RF devices to set off explosives.

6.3.2.8 Potentially explosive atmospheres

Turn your terminal **OFF** when in any area with a potentially explosive atmosphere. It is rare, but your modem or its accessories could generate sparks. Sparks in such areas could cause an explosion or fire resulting in bodily injuries or even death.

Areas with a potentially explosive atmosphere are often, but not always, clearly marked. They include fuelling areas such as petrol stations ; below decks on boats ; fuel or chemical transfer or storage facilities ; and areas where the air contains chemicals or particles, such as grain, dust, or metal powders.

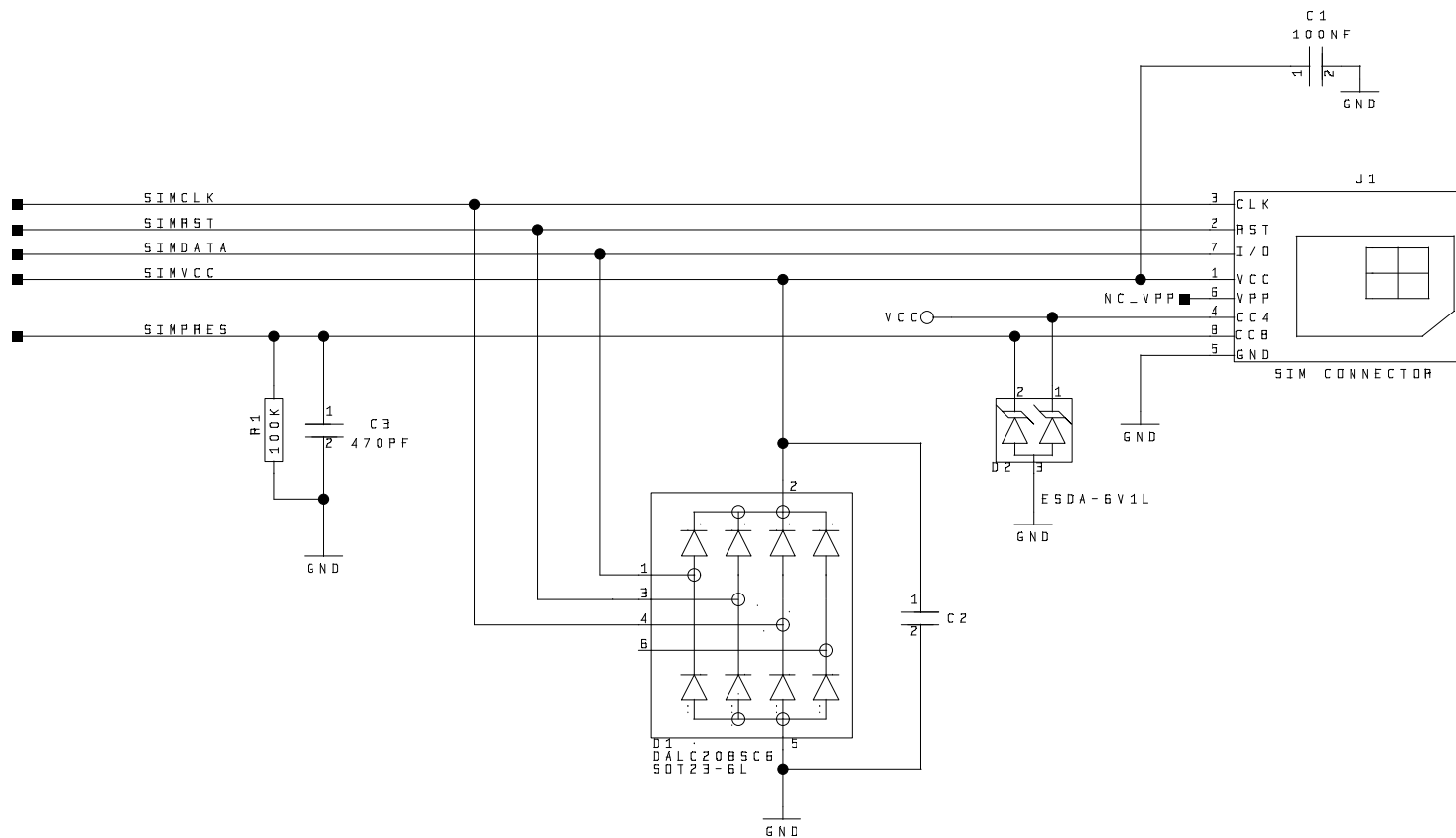
Do not transport or store flammable gas, liquid, or explosives, in the compartment of your vehicle which contains your terminal or accessories.

Before using your terminal in a vehicle powered by liquefied petroleum gas (such as propane or butane) ensure that the vehicle complies with the relevant fire and safety regulations of the country in which the vehicle is to be used.

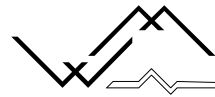
6.4 Application notes for the SIM interface

The next 2 pages are application notes to interface the module with SIM cards:

- application note #1: interface with 3V SIMs
- application note #2: interface with 3V/5V SIMs



- C1 HAS TO BE CLOSE J1
- ESD PROTECTION CAPACITANCE IS LESS THAN 10PF FOR SIMDATA AND SIMCLK
- ESD PROTECTION HAS TO BE CLOSE J1
- 470nF Max for C2



WAVECOM

The shock wave in the wireless world

| | |
|---|---|
| PROJECT: APPLICATION NOTE | Sheet: 1/1 |
| SCHEMATIC: SIM 3V ONLY (WISMD2D) | |
| WAVECOM 39 Rue du Gouverneur Eboe 92130 ISSY LES MOULINEAUX FRANCE | Date: 10/10/2001 Version: 1.0 Eng:FDL |

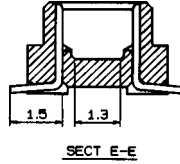
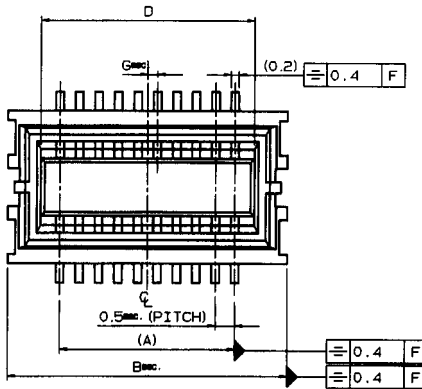
6.5 General Purpose Connector data sheet

The next 6 pages are the KYOCERA/ELCO data sheets for the GPC (also available from <http://www.avxcorp.com>).

0,5 mm Spacing

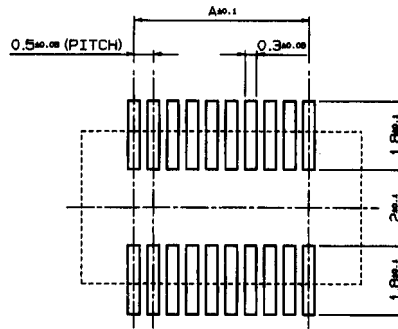
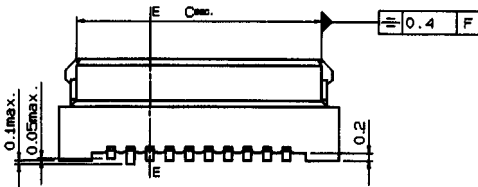
SERIES 5087

Surface Mount Vertical Plug

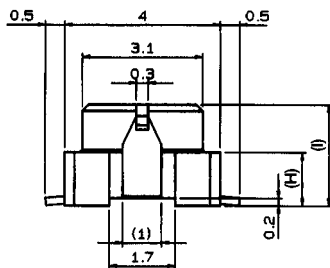


Specifications:

- 1000 per Tape and Reel
- Voltage - 50 V
- Current Rating - 0.4 A
- Dielectric Withstanding Voltage - 500 V
- Operating Temperature - (-25°C ~ +85°C)
- Contact Material - phosphor bronze
- Insulator Material - PPS (UL 94 V-0)



MOUNTING LAYOUT



| No. of Pos. | P/N | A | B | C | D | G |
|-------------|---------------------|-----------|-----------|-----------|-----------|------------|
| 20 | 10 5087 020 XX0 861 | 4.5/.177 | 7.2/.283 | 6.2/.244 | 5.5/.217 | 0.25/.0098 |
| 30 | 10 5087 030 XX0 861 | 7.0/.276 | 9.7/.382 | 8.7/.343 | 8.0/.315 | 0.50/.0196 |
| 36 | 10 5087 036 XX0 861 | 8.5/.335 | 11.2/.441 | 10.2/.402 | 9.5/.374 | 0.25/.0098 |
| 40 | 10 5087 040 XX0 861 | 9.5/.374 | 12.2/.480 | 11.2/.441 | 10.5/.414 | 0.25/.0098 |
| 50 | 10 5087 050 XX0 861 | 12.0/.472 | 14.7/.579 | 13.7/.539 | 13.0/.512 | 0.50/.0196 |
| 60 | 10 5087 060 XX0 861 | 14.5/.571 | 17.2/.677 | 16.2/.638 | 15.5/.610 | 0.25/.0098 |

Dimensions millimeters/inches

ORDERING CODE

Typical Example

14

5087

0XX

2XX

861

14: PLUG - Tape and Reel

NUMBER OF CONTACTS:

40, 60 : 3.0mm Stack

36, 40, 50 : 3.5mm Stack

20, 30, 36,

50, 60 : 4.0mm Stack

2: Without Adhesive Tape

9: Adhesive Cover Tape

VARIATION CODE:

30 H .9 I 2.15

35 1.4 2.7

40 1.9 3.2

PLATING VARIATION:

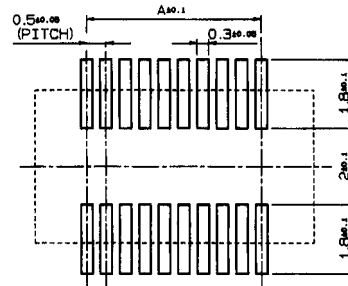
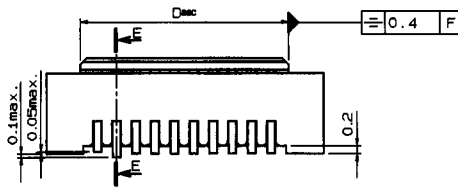
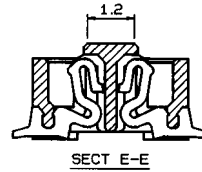
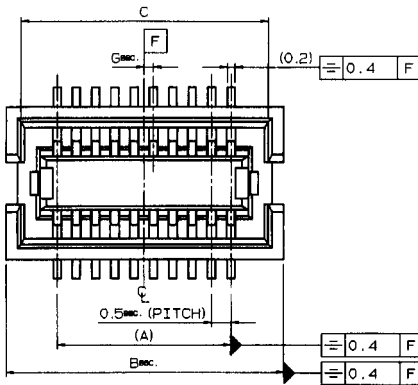
861: 15 microinches of gold with gold flash tails

Consult factory for other sizes

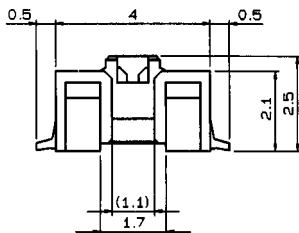
Surface Mount Vertical Receptacle

Specifications:

- 1000 per Tape and Reel
- Voltage - 50 V
- Current Rating - 0.4 A
- Dielectric Withstanding Voltage - 500 V
- Operating Temperature - (-25°C ~ +85°C)
- Contact Material - phosphor bronze
- Insulator Material - PPS (UL 94 V-0)



MOUNTING LAYOUT



| No. of Pos. | P/N | A | B | C | D | G |
|-------------|---------------------|-----------|-----------|-----------|-----------|------------|
| 20 | 20 5087 020 x00 861 | 4.5/.177 | 7.2/.283 | 6.4/.252 | 5.4/.213 | 0.25/.0098 |
| 30 | 20 5087 030 x00 861 | 7.0/.276 | 9.7/.382 | 8.9/.350 | 7.9/.311 | 0.50/.0196 |
| 36 | 20 5087 036 x00 861 | 8.5/.335 | 11.2/.441 | 10.4/.409 | 9.4/.370 | 0.25/.0098 |
| 40 | 20 5087 040 x00 861 | 9.5/.374 | 12.2/.480 | 11.4/.449 | 10.4/.409 | 0.25/.0098 |
| 50 | 20 5087 050 x00 861 | 12.0/.472 | 14.7/.579 | 13.9/.547 | 12.9/.508 | 0.50/.0196 |
| 60 | 20 5087 060 x00 861 | 14.5/.570 | 17.2/.677 | 16.4/.646 | 15.4/.606 | 0.25/.0098 |

Dimensions millimeters/inches

ORDERING CODE

Typical Example

24

5087

0XX

200

861

24: Receptacle - Tape and Reel

NUMBER OF CONTACTS:

20, 30, 36, 40, 50, 60

2: Without Adhesive Tape

9: Adhesive Cover Tape

PLATING VARIATION:

861: 15 microinches of gold with gold flash tails

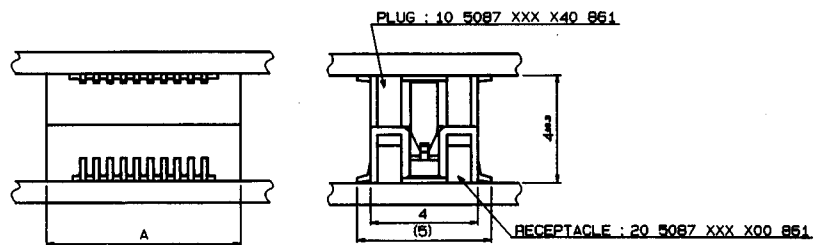
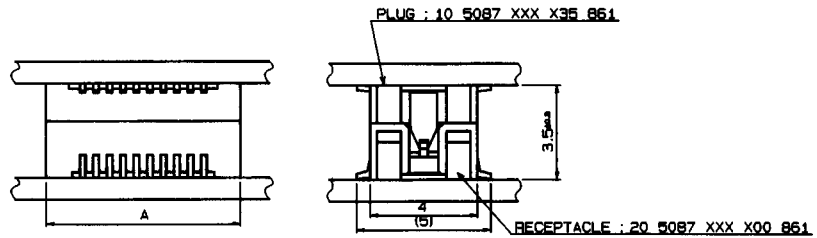
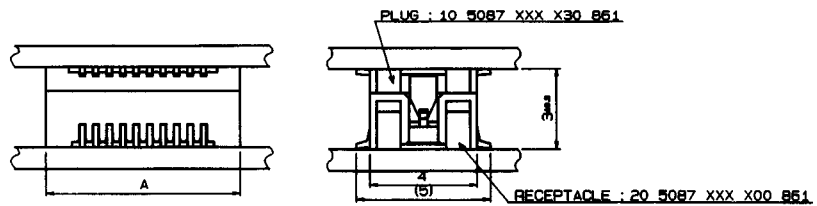
Consult factory for other sizes

0,5 mm Spacing

Applications

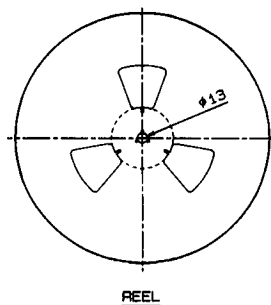
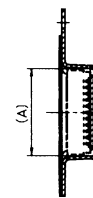
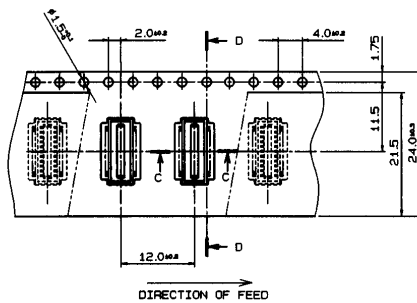
| | P/N | Stacking Height |
|-------|---------------------|-----------------|
| PLUG | 10 5087 xxx x30 861 | 3.0 |
| RECE. | 20 5087 xxx x00 861 | |
| PLUG | 10 5087 xxx x35 861 | 3.5 |
| RECE. | 20 5087 xxx x00 861 | |
| PLUG | 10 5087 xxx x40 861 | 4.0 |
| RECE. | 20 5087 xxx x00 861 | |

| No. of Pos. | A |
|-------------|----------|
| 20 | 7.2/283 |
| 30 | 9.7/382 |
| 36 | 11.2/441 |
| 40 | 12.2/480 |
| 50 | 14.7/579 |
| 60 | 17.2/677 |

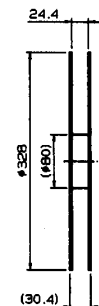


0,5 mm Spacing

Tape and Reel

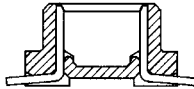
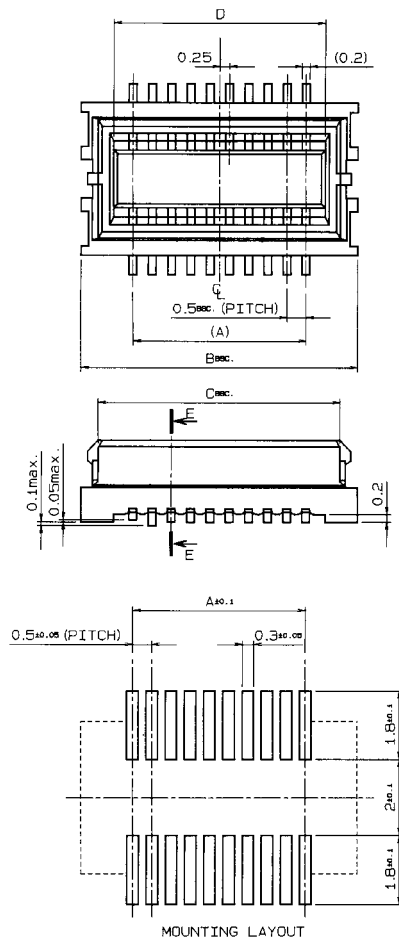


REEL



Super Micro Connectors 0.5mm Pitch

Series 5087 Plug



ORDERING CODE

14 5087 0XX X XX 8XX

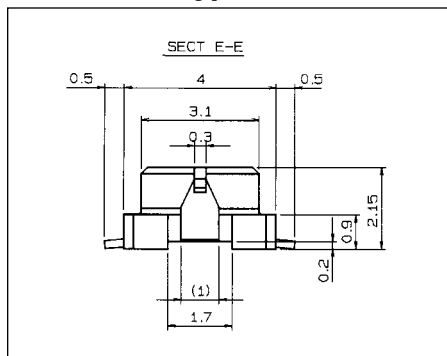
- FINISH
 - 861 = Ni Under Coated
1.25µm min.
Gold-Mating Area
Au 0.38µm min.
 - 829 = Ni Under Coated
1.25µm min.
Gold-Mating Area
Au 0.1µm min.
- VARIATION
 - 30 : H = 3.0mm
 - 35 : H = 3.5mm
 - 40 : H = 4.0mm
- TYPE
 - 0 = without Boss with Retention Clip
 - 2 = without Boss, Retention Clip
 - 9 = without Boss, Retention Clip, with Adhesive Tape

NUMBER OF POSITIONS
(20, 30, 32, 36, 40, 50, 60)

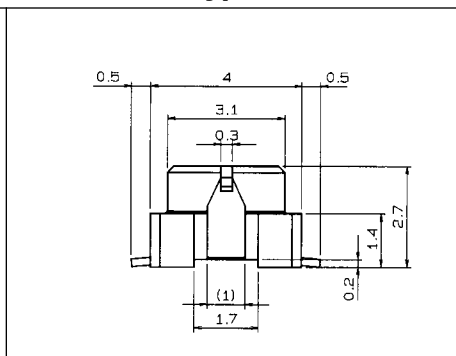
SERIES
TAPE AND REEL
14 = Plug

- A = 0.5 (± -1)
- B = 0.5 (± -1)+2.7
- C = 0.5 (± -1)+1.7
- D = 0.5 (± -1)+1.0

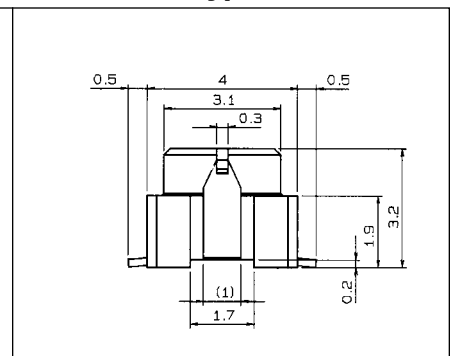
H = 3.0mm Type



H = 3.5mm Type



H = 4.0mm Type

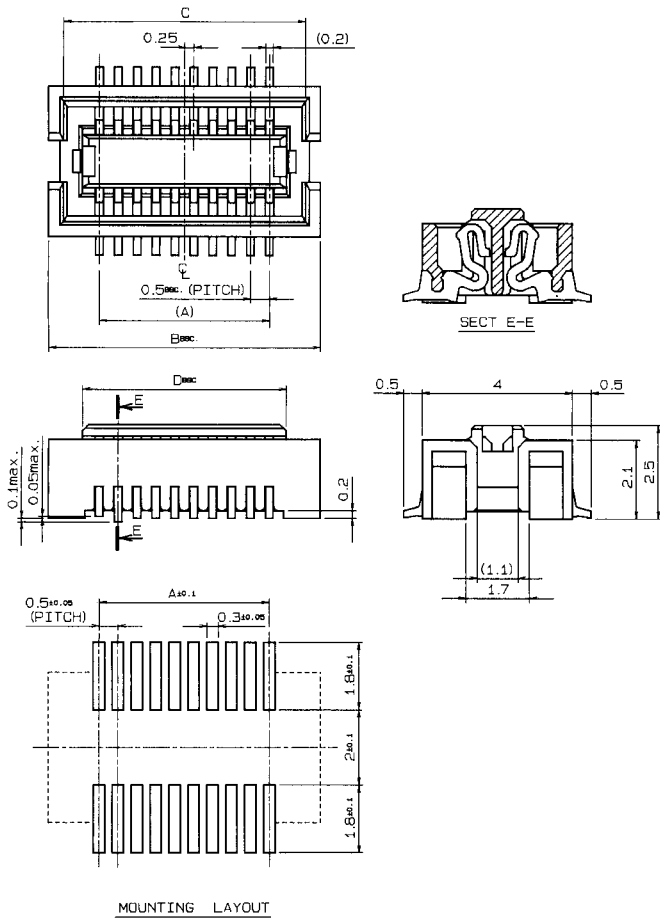


Additional information on this product is available from AVX's catalog or AVX's FAX Service. Call 1-800-879-1613 and request document #269. Visit our website <http://www.avxcorp.com>

ELCO

Super Micro Connectors 0.5mm Pitch

Series 5087 Receptacle H = 3.0 ~ 4.0mm Type



ORDERING CODE

24 **5087** **0XX** **X** **00** **8XX**
 — FINISH
 861 = Ni Under Coated
 1.25µm min.
 Gold-Mating Area
 Au 0.38µm min.
 829 = Ni Under Coated
 1.25µm min.
 Gold-Mating Area
 Au 0.1µm min.
 — VARIATION
 H = 3.0 ~ 4.0mm
 — TYPE 0 = without Boss with Retention Clip
 2 = without Boss, Retention Clip
 9 = without Boss, Retention Clip, with Adhesive Tape
 — NUMBER OF POSITIONS
 (20, 30, 32, 36, 40, 50, 60)
 — SERIES
 — TAPE AND REEL
 24 = Receptacle

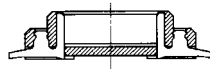
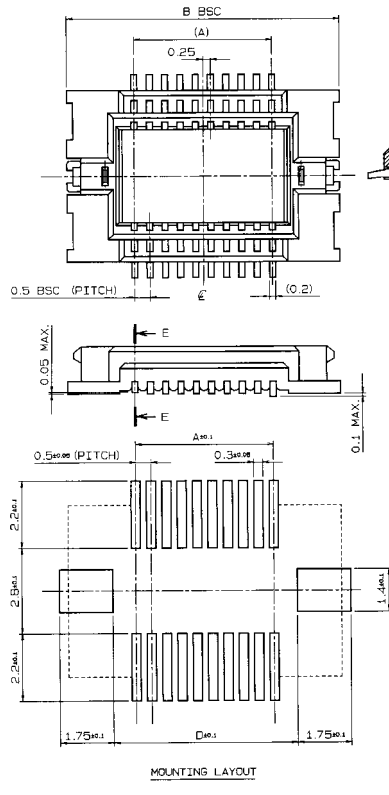
A = 0.5 (± -1)
 B = A + 2.7
 C = A + 1.9
 D = A + 0.9

Additional information on this product is available from AVX's catalog or AVX's FAX Service. Call 1-800-879-1613 and request document #270. Visit our website <http://www.avxcorp.com>

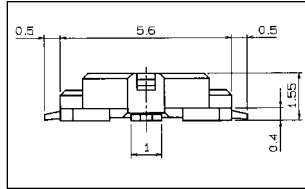
ELCO

Super Micro Connectors 0.5mm Pitch

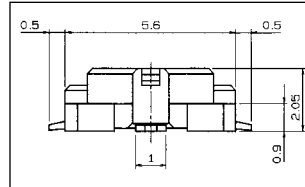
Series 5087 Plug



H = 2.0mm Type



H = 2.5mm Type



A = 0.5 (±1)
 B = 0.5 (±1)+4.4
 D = 0.5 (±1)+1.5

ORDERING CODE

14 5087 0XX X XX 8XX

FINISH
 861 = Ni Under Coated
 1.25µm min.
 Gold-Mating Area
 Au 0.38µm min.
 829 = Ni Under Coated
 1.25µm min.
 Gold-Mating Area
 Au 0.1µm min.

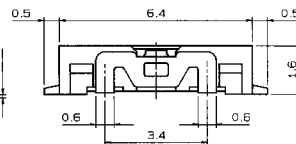
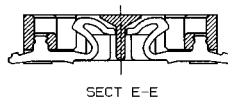
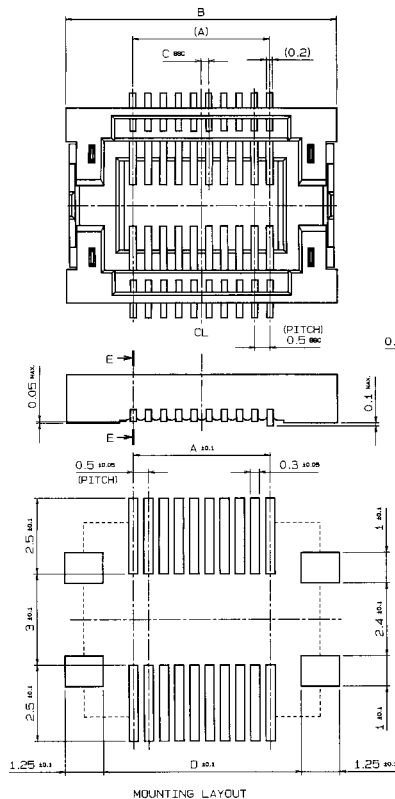
VARIATION
 20 : H = 2.0mm
 25 : H = 2.5mm

TYPE 0 = without Boss with Retention Clip
 2 = without Boss, Retention Clip
 9 = without Boss, Retention Clip, with Adhesive Tape

NUMBER OF POSITIONS
 (10*, 20, 30, 40, 50, 60) *2.0mm H only

SERIES
 TAPE AND REEL
 14 = Plug

Series 5087 Receptacle H = 2.0 ~ 2.5mm Type



ORDERING CODE

24 5087 0XX X 01 8XX

FINISH
 861 = Ni Under Coated
 1.25µm min.
 Gold-Mating Area
 Au 0.38µm min.
 829 = Ni Under Coated
 1.25µm min.
 Gold-Mating Area
 Au 0.1µm min.

VARIATION
 H = 2.0 ~ 2.5mm

TYPE 0 = without Boss with Retention Clip
 2 = without Boss, Retention Clip
 9 = without Boss, Retention Clip, with Adhesive Tape

NUMBER OF POSITIONS
 (10, 20, 30, 40, 50, 60)

SERIES
 TAPE AND REEL
 24 = Receptacle

Additional information on this product is available from AVX's catalog or AVX's FAX Service. Call 1-800-879-1613 and request document #271. Visit our website <http://www.avxcorp.com>

ELCO